AMD 890FX Databook

Technical Reference Manual
Rev 3.00

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Chapter 1
Overview

1.1 Introducing AMD 890FX

AMD 890FX (referred to by its code name "RD890" in this document) is the system logic of the latest platform from AMD that enables its next generation CPUs with the leading ATI CrossFire™ solutions. The RD890 has a total of 42 PCI Express® lanes: 10 lanes are dedicated for external PCIe devices, and the rest support 2 x16 PCIe links or 4 x8 PCIe links for the ultimate graphics setup. With support for a four-lane A-Link Express III interface to AMD's Southbridges such as the SB800, the RD890 guarantees separate bandwidth for peripherals, graphics, and General Purpose Graphics Processor Unit (GPGPU). The RD890 also comes equipped with the new HyperTransport™ 3 and PCIe Gen 2 technologies, with the ability for high system overclocking to deliver leadership performance. All of these are achieved by a highly integrated, thermally efficient design in a 29mm x 29mm package.

The RD890 also supports a revision 1.26 compliant IOMMU (Input/Output Memory Management Unit) implementation for address translation and protection services. This feature allows virtual addresses from PCI Express endpoint devices to be translated to physical memory addresses. On-chip caching of address translations is provided to improve I/O performance. The device is also compliant with revision 1.0 of the PCI Express Address Translation Services (ATS) specification to enable ATS-compliant endpoint devices to cache address translation. These features enhance memory protection and support hardware-based I/O virtualization when combined with appropriate operating system or hypervisor software. Combined with AMD Virtualization™ (AMD-V™) technology, these features are designed to provide comprehensive platform level virtualization support.

1.2 RD890 Features

1.2.1 CPU Interface

- Supports 16-bit up/down HyperTransport™ (HT) 3.0 interface up to 5.2 GT/s.
- Supports 200, 400, 600, 800, and 1000 MHz HT1 frequencies.
- Supports 1200, 1400, 1600, 1800, 2000, 2200, 2400, and 2600 MHz HT3 frequencies.
- Supports "Shanghai" and subsequent series of AMD server/workstation and desktop processors through sockets F, AM3, G34, and C32.
- Supports AMD Phenom™ and later desktop processors.
- Supports LDTSTOP interface and CPU throttling.
- Supports broadcast memory write to the graphics ports.

1.2.2 PCI Express® Interface

- Supports PCIe Gen 2 (version 2.0).
- Optimized peer-to-peer and general purpose link performance.
- Supports 2 x16 graphics links for simultaneous operation of 2 graphics cards. They are also configurable to operate as 4 x8 graphics links.
- Supports 10 PCI E Gen 2 general purpose lanes, supporting up to 7 devices on specific ports (possible configurations are described in *Section 2.3, "PCI Express®"*).
- Supports a revision 1.26 compliant IOMMU (Input/Output Memory Management Unit) implementation for address translation and protection services. Please refer to the *AMD I/O Virtualization Technology (IOMMU) Specification* for more details.

1.2.3 A-Link Express III Interface

- One x4 A-Link Express III interface for connection to an AMD Southbridge. The A-Link Express III is a proprietary interface developed by AMD based on the PCI Express technology, with additional Northbridge-Southbridge

messaging functionalities. It supports the PCIe Gen 2 transfer rate of 5 GT/s, and is backward compatible with the A-Link Express II interface.

1.2.4 Power Management Features

- Fully supports ACPI states S1, S3, S4, and S5.
- The Chip Power Management Support logic supports four device power states defined for the OnNow Architecture—On, Standby, Suspend, and Off. Each power state can be achieved by software control bits.
- Supports AMD Cool'n'Quiet™ technology via FID/VID change.
- Clocks are controlled dynamically using a mechanism that is transparent to the software. The ASIC hardware detects idle blocks and turns off the clocks to those blocks in order to reduce power consumption.
- Supports dynamic lane reduction for the PCIe interfaces, adjusting to the task the number of lanes employed.

1.2.5 PC Design Guide Compliance

The RD890 complies with all relevant Windows Logo Program (WLP) requirements from Microsoft® for WHQL certification.

1.2.6 Test Capability Features

The RD890 has a variety of test modes and capabilities that provide a very high fault coverage and low DPM (Defect Per Million) ratio:

- Full scan implementation on the digital core logic which provides about 97% fault coverage through ATPG (Automatic Test Pattern Generation Vectors).
- Dedicated test logic for the on-chip custom memory macros to provide complete coverage on these modules.
- A JTAG test mode in order to allow board level testing of neighboring devices.
- An XOR tree test mode on all the digital I/O's to allow for proper soldering verification at the board level.
- Access to the analog modules and PLLs in the RD890 in order to allow full evaluation and characterization of these modules.
- IDDQ mode support to allow chip evaluation through current leakage measurements.
- Highly advanced signal observability through the debug port.

These test modes can be accessed through the settings of the instruction register of the JTAG circuitry.

1.2.7 Packaging

- Single chip solution in 65nm, 1.1V CMOS technology.
- Flip chip design in a 29mm x 29mm 692-FCBGA package.

1.3 Software Features

- Supports Microsoft Windows® XP, Windows Vista®, and Windows® 7.
- Supports corporate manageability requirements such as DMI.
- ACPI support.
- Full write combining support for maximum performance.
- Comprehensive OS and API support.
- Extensive Power Management support.

1.4 Device ID

The RD890 is a member of the AMD chipset family, which consists of different devices designed to support different platforms. Each device is identified by the device ID, which is stored in the NB_DEVICE_ID register. The device ID for the RD890 is 5A11h.

1.5 Branding Diagrams

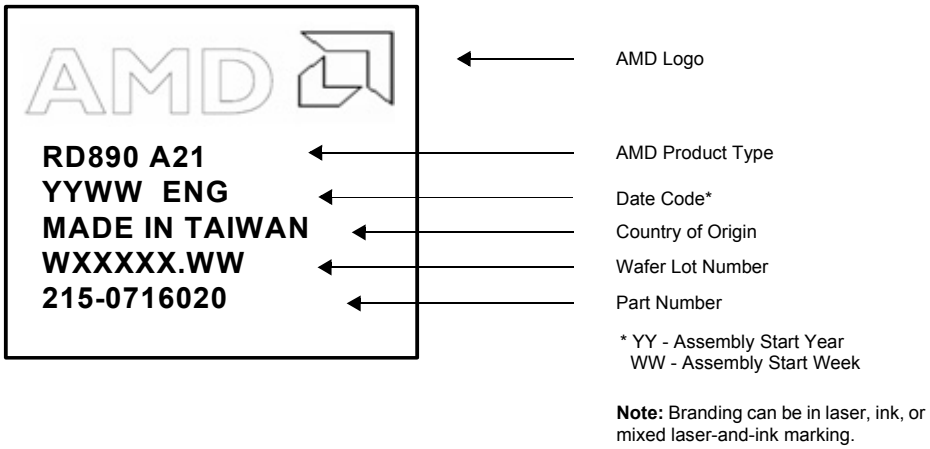

Figure 1-1 RD890 Branding Diagram for A21 Engineering Sample

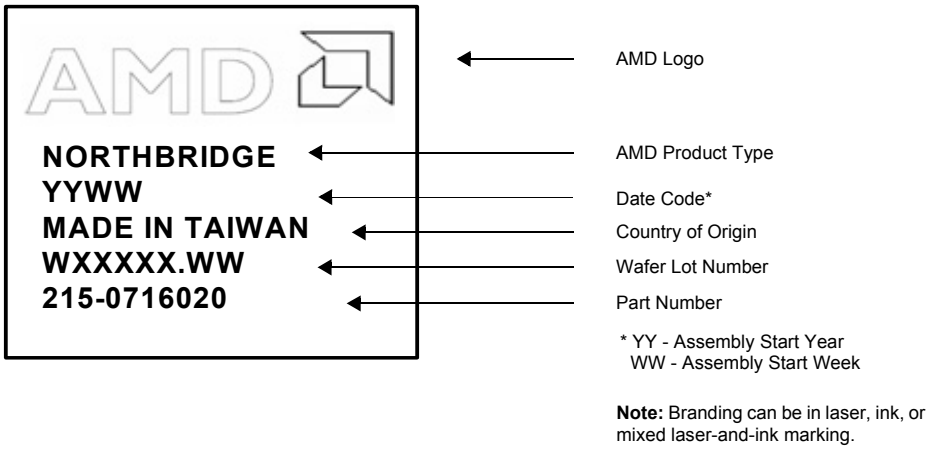

Figure 1-2 RD890 Branding Diagram for A21 Production Sample

1.6 Conventions and Notations

The following sections explain the conventions used throughout this manual.

1.6.1 Pin Names

Pins are identified by their pin names or ball references. All active-low signals are identified by the suffix '#' in their names (e.g., SYSRESET#).

1.6.2 Pin Types

The pins are assigned different codes according to their operational characteristics. These codes are listed in *Table 1-1*.

Table 1-1 Pin Type Codes

Code	Pin Type
I	Digital Input
O	Digital Output
I/O	Bi-Directional Digital Input or Output
M	Multifunctional
Pwr	Power
Gnd	Ground
A-O	Analog Output
A-I	Analog Input
A-I/O	Analog Bi-Directional Input/Output
A-Pwr	Analog Power
A-Gnd	Analog Ground
Other	Pin types not included in any of the categories above

1.6.3 Numeric Representation

Hexadecimal numbers are appended with "h" whenever there is a risk of ambiguity. Other numbers are in decimal.

Pins of identical functions but different trailing digits (e.g., DFT_GPIO0, DFT_GPIO1, ...DFT_GPIO5) are referred to collectively by specifying their digits in square brackets and with colons (i.e., "DFT_GPIO[5:0]"). A similar short-hand notation is used to indicate bit occupation in a register. For example, NB_COMMAND[15:10] refers to the bit positions 10 through 15 of the NB_COMMAND register.

1.6.4 Hyperlinks

Phrases or sentences in *blue italic font* are hyperlinks to other parts of the manual. Users of the PDF version of this manual can click on the links to go directly to the referenced sections, tables, or figures.

1.6.5 Acronyms and Abbreviations

The following is a list of the acronyms and abbreviations used in this manual.

Table 1-2 Acronyms and Abbreviations

Acronym	Full Expression
ACPI	Advanced Configuration and Power Interface
ASPM	Active State Power Management
A-Link-E	A-Link Express interface between the Northbridge and Southbridge.
BGA	Ball Grid Array
BIOS	Basic Input Output System. Initialization code stored in a ROM or Flash RAM used to start up a system or expansion card.
BIST	Built In Self Test.
DBI	Dynamic Bus Inversion
DPM	Defects per Million
EPROM	Erasable Programmable Read Only Memory
FCBGA	Flip Chip Ball Grid Array
FIFO	First In, First Out
VSS	Ground
GPIO	General Purpose Input/Output
HT	HyperTransport™ interface
IDDQ	Direct Drain Quiescent Current
IOMMU	Input/Output Memory Management Unit
JTAG	Joint Test Access Group. An IEEE standard.

Table 1-2 Acronyms and Abbreviations (Continued)

Acronym	Full Expression
MB	Mega Byte
NB	Northbridge
PCI	Peripheral Component Interface
PCIe®	PCI Express®
PLL	Phase Locked Loop
POST	Power On Self Test
PD	Pull-down Resistor
PU	Pull-up Resistor
RAS	Reliability, Availability and Serviceability
SB	Southbridge
TBA	To Be Added
VRM	Voltage Regulation Module

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Chapter 2
Functional Descriptions

This chapter describes the functional operation of the major interfaces of the RD890 system logic chip. *Figure 2-1* illustrates the RD890 internal blocks and interfaces.

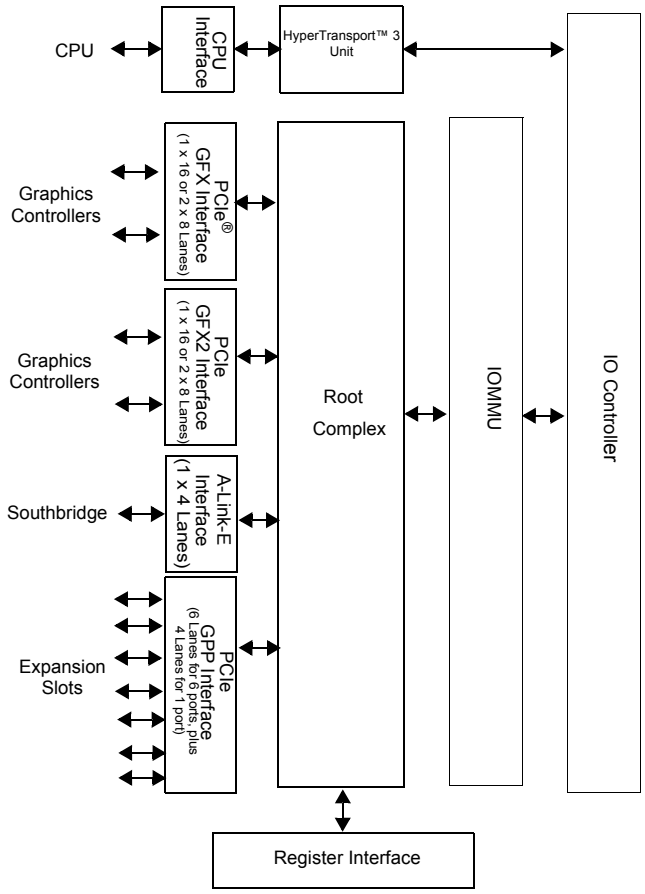

Figure 2-1 RD890 Internal Blocks and Interfaces

2.1 HyperTransport™ Interface

2.1.1 Overview

The RD890 is optimized to interface with the AMD Phenom™ and later desktop processors. The supports HyperTransport™ 3 (HT3), as well as HyperTransport 1 (HT1) for backward compatibility and for initial boot-up. For a detailed description of the interface, please refer to the *HyperTransport I/O Link Specification* from the HyperTransport Consortium. *Figure 2-2, "HyperTransport™ Interface Block Diagram,"* illustrates the basic blocks of the host bus interface of the RD890.

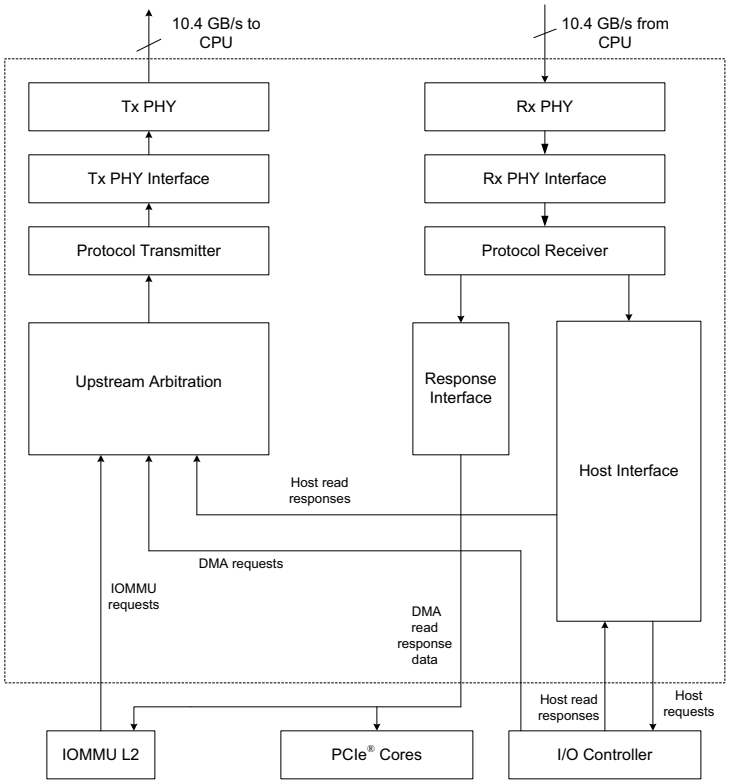

Figure 2-2 HyperTransport™ Interface Block Diagram

The RD890 HyperTransport bus interface consists of 16 unidirectional differential Command/Address/Data pins, and 2 differential Control pins and 2 differential Clock pins in both the upstream and downstream directions. On power up, the link is 8-bit wide and runs at a default speed of 400MT/s in HyperTransport 1 mode. After negotiation, carried out by the HW and SW together, the link width can be brought up to the full 16-bit width and the interface can run up to 5.2GT/s in HyperTransport 3 mode. In HyperTransport 1 mode, the interface operates by clock-forwarding while in HyperTransport 3 mode, the interface operates by dynamic phase recovery, with frequency information propagated over the clock pins. The interface is illustrated below in *Figure 2-3, "RD890 HyperTransport™ Interface Signals."* The signal name and direction for each signal is shown with respect to the RD890. Detailed descriptions of the signals are given in *Section 3.3, "CPU HyperTransport™ Interface," on page 3-4*.

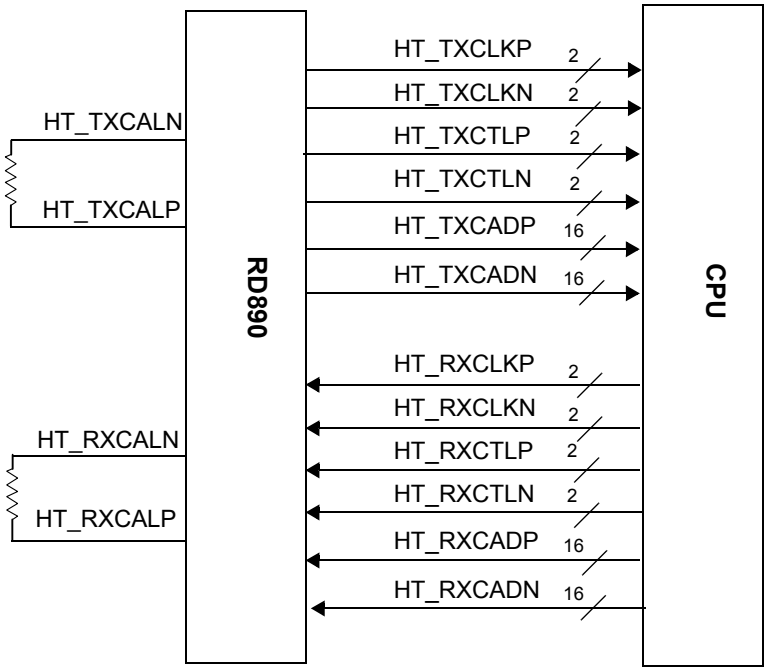

Figure 2-3 RD890 HyperTransport™ Interface Signals

The RD890 HyperTransport interface has the following features:

- HyperTransport 3.0 compliant
- 16-bit and 8-bit link widths supported. Width for each direction of the link is independently controlled.
- 400MT/s to 5.2GT/s link speeds in increments of 400MT/s (up to 2GT/s only for HyperTransport 1 mode)
- DC-coupled HyperTransport mode only
- UnitID clumping for x16 PCI Express® ports
- Isochronous flow-control mode for Southbridge audio and IOMMU 64-bit address extension support (52-bit physical addressing)
- Link disconnection with tristate, LS0, LS1, LS2, and LS3 low-power modes
- Error retry in HyperTransport 3 mode
- Full HyperTransport-defined BIST support for both internal and external loopback modes

2.1.2 HyperTransport™ Flow Control Buffers

The RD890 HTIU implements the following flow control buffers in its receiver:

Table 2-1 RD890 HyperTransport™ Flow Control Buffers

Flow Control Buffer Type	Posted	Non-Posted	Response
Cmd	16	16	Advertise 63 credits.
Data	16	1	Advertise 63 credits.
ISOC Cmd	0	0	Advertise 63 credits.
ISOC Data	0	0	Advertise 63 credits.

2.2 IOMMU

The RD890's IOMMU (Input/Output Memory Management Unit) block provides address translation and protection services as described in version 1.26 of the *AMD I/O Virtualization Technology (IOMMU) Specification*. The RD890 also supports the *PCI Express Address Translation Services 1.0 Specification*, which allows the supporting of endpoint devices to request and cache address translations.

When DMA requests containing virtual addresses are received, the IOMMU looks up the page translation tables located in the system memory in order to convert the virtual addresses into physical addresses and to verify access privileges. On-chip caching is provided in order to speed up translation and reduce or eliminate the number of system memory accesses required. Every PCIe core contains a local translation cache, and the RD890 also contains a shared global translation cache.

The RD890 supports up to 2^{16} domains, each of which can utilize a separate 64-bit virtual address space. It supports a 52-bit physical address space.

2.3 PCI Express®

2.3.1 PCIe® Ports

In total, there are 12 PCIe® ports on the RD890, divided into 5 groups and implemented in hardware as 5 separate cores:

- PCIE-GFX: 2 graphics ports, 16 lanes in total. Width of each port is x8. In the default configuration, the 2 ports are combined to provide a 1 x16 port.
- PCIE-GFX2: 2 graphics ports, 16 lanes in total. Width of each port is x8. In the default configuration, the 2 ports are combined to provide a 1 x16 port.
- PCIE-GPPa: 6 general purpose ports, with 6 lanes in total. They support 6 different configurations with respect to link widths: 4:2, 4:1:1, 2:2:2, 2:2:1:1, 2:1:1:1:1, and 1:1:1:1:1:1 (default configuration). See *Table 2-2, "Possible Configurations for the PCI Express® General Purpose Links," on page 2-5* and *Table 3-12, "Strap Definition for STRAP_PCIE_GPP_CFG," on page 3-10*.
- PCIE-GPPb: 1 general purpose port, with 4 lanes in total. Width of the port is x4.

Table 2-2 Possible Configurations for the PCI Express® General Purpose Links

<table>
<tr><th>PCIe® Core</th><th>Physical Lane</th><th>Config. B</th><th>Config. C</th><th>Config. C2</th><th>Config. E</th><th>Config. K</th><th>Config. L</th></tr>
<tr><td rowspan="6">GPPa</td><td>GPP0</td><td rowspan="4">x4</td><td rowspan="4">x4</td><td rowspan="2">x2</td><td rowspan="2">x2</td><td rowspan="2">x2</td><td>x1</td></tr>
<tr><td>GPP1</td><td>x1</td></tr>
<tr><td>GPP2</td><td rowspan="2">x2</td><td>x1</td><td rowspan="2">x2</td><td>x1</td></tr>
<tr><td>GPP3</td><td>x1</td><td>x1</td></tr>
<tr><td>GPP4</td><td rowspan="2">x2</td><td>x1</td><td rowspan="2">x2</td><td>x1</td><td>x1</td><td>x1</td></tr>
<tr><td>GPP5</td><td>x1</td><td>x1</td><td>x1</td><td>x1</td></tr>
<tr><td rowspan="4">GPPb</td><td>GPP6</td><td rowspan="4">x4</td><td rowspan="4">x4</td><td rowspan="4">x4</td><td rowspan="4">x4</td><td rowspan="4">x4</td><td rowspan="4">x4</td></tr>
<tr><td>GPP7</td></tr>
<tr><td>GPP8</td></tr>
<tr><td>GPP9</td></tr>
</table>

- PCIE-SB: The Southbridge port provides a dedicated x4 link to the Southbridge (also referred to as the "A-Link Express III interface").

Each port supports the following PCIe functions:

- PCIe Gen 1 and Gen 2 link speeds
- ASPM L0s and L1 states
- ACPI power management
- Endpoint and root complex initiated dynamic link degradation
- Lane reversal
- Alternative Routing-ID Interpretation (ARI)

The PCIE-GFX and PCIE-GFX2 ports also support the ATI CrossFire™ technology.

2.3.2 PCIe® Reset Signals

Reset signals to PCIe slots, as well as embedded PCIe devices, must be controlled through one or more software-controllable GPIO pins instead of the global system reset. It is recommended that unique GPIO pins be used for each slot or device. The RD890 has four GPIO pins that may be used for the purpose of driving reset signals (PCIE_GPIO_RESET[5:4] and PCIE_GPIO_RESET[2:1]). Additional reset GPIO pins may be driven by platform-specific means such as a super I/O or an I/O expander.

2.4 External Clock Chip

On the RD890 platform, an external clock chip provides the CPU, PCI Express, and A-Link Express III reference clocks. For requirements on the clock chip, please refer to the *700 and 800 Series IGP Express AMD Platform External Clock Generator Requirements Specification for Client Platforms*.

Chapter 3
Pin Descriptions and Strap Options

This chapter gives the pin descriptions and the strap options for the RD890. To jump to a topic of interest, use the following list of hyperlinked cross references:

3.1 Pin Assignment Top View

	1	2	3	4	5	6	7	8	9	10	11	12	13	14
A			VDDPCIE	GFX_TX6P	VSS	GFX_TX5P	VSS	GFX_TX3P	VSS	GFX_TX1P	VSS	VDDA18PCIE	VDDA18PCIE	VSS
B		VDDPCIE	VSS	GFX_TX6N	GFX_RX6P	GFX_TX5N	GFX_TX4P	GFX_TX3N	GFX_TX2P	GFX_TX1N	GFX_TX0P	VDDA18PCIE	VDDA18PCIE	VSS
C	VDDPCIE	VSS	VDDPCIE	VSS	GFX_RX6N	VSS	GFX_TX4N	VSS	GFX_TX2N	VSS	GFX_TX0N	VDDA18PCIE	VDDA18PCIE	VSS
D	GFX_RX7N	GFX_RX7P	VSS	VDDPCIE	VSS	GFX_RX5P	VSS	GFX_RX3P	VSS	GFX_RX1P	VSS	VDDA18PCIE	VDDA18PCIE	VSS
E	VSS	GFX_TX7N	GFX_TX7P	VSS	VDDPCIE	GFX_RX5N	GFX_RX4P	GFX_RX3N	GFX_RX2P	GFX_RX1N	GFX_RX0P	VDDA18PCIE	VDDA18PCIE	PCE_TCALRN
F	GFX_TX8N	GFX_TX8P	VSS	GFX_RX8N	GFX_RX8P	VDDPCIE	GFX_RX4N	VSS	GFX_RX2N	VSS	GFX_RX0N	VDDA18PCIE	VDDA18PCIE	PCE_TCALRP
G	VSS	GFX_TX9N	GFX_TX9P	VSS	GFX_RX9N	GFX_RX9P	VDDPCIE	VDDPCIE	VSS	VDDPCIE	VSS	VDDA18PCIE	VDDA18PCIE	VDDA18PCIE
H	GFX_TX10N	GFX_TX10P	VSS	GFX_RX10N	GFX_RX10P	VSS	VDDPCIE	GFX_REFCLKN	VDDPCIE	VSS	VDDPCIE	VDDA18PCIE	VDDA18PCIE	VDDA18PCIE
J	VSS	GFX_TX11N	GFX_TX11P	VSS	GFX_RX11N	GFX_RX11P	VSS	GFX_REFCLKP						
K	GFX_TX12N	GFX_TX12P	VSS	GFX_RX12N	GFX_RX12P	VSS	VDDPCIE	VSS						
L	VSS	GFX_TX13N	GFX_TX13P	VSS	GFX_RX13N	GFX_RX13P	VSS	VDDPCIE			VDDA18PCIE	VSS	VSS	VDDC
M	GFX_TX14N	GFX_TX14P	VSS	GFX_RX14N	GFX_RX14P	VSS	VDDPCIE	VSS			VSS	VSS	VDDC	VSS
N	VSS	GFX_TX15N	GFX_TX15P	VSS	GFX_RX15N	GFX_RX15P	VSS	VDDPCIE			VSS	VDDC	VSS	VDDC
P	GFX2_TX0N	GFX2_TX0P	VSS	GFX2_RX0N	GFX2_RX0P	VSS	VDDPCIE	VSS			VSS	VSS	VDDC	VSS
R	VSS	GFX2_TX1N	GFX2_TX1P	VSS	GFX2_RX1N	GFX2_RX1P	VSS	VDDPCIE			VSS	VDDC	VSS	VDDC
T	GFX2_TX2N	GFX2_TX2P	VSS	GFX2_RX2N	GFX2_RX2P	VSS	VDDPCIE	VSS			VSS	VSS	VDDC	VSS
U	VSS	GFX2_TX3N	GFX2_TX3P	VSS	GFX2_RX3N	GFX2_RX3P	VSS	GFX2_RFCLKN			VSS	VSS	VSS	VDDC
V	GFX2_TX4N	GFX2_TX4P	VSS	GFX2_RX4N	GFX2_RX4P	VSS	VDDPCIE	GFX2_RFCLKP			VDDA18PCIE	VSS	VSS	VSS
W	VSS	GFX2_TX5N	GFX2_TX5P	VSS	GFX2_RX5N	GFX2_RX5P	VSS	VDDPCIE						
Y	GFX2_TX6N	GFX2_TX6P	VSS	GFX2_RX6N	GFX2_RX6P	VSS	VDDPCIE	VSS						
AA	VSS	GFX2_TX7N	GFX2_TX7P	VSS	GFX2_RX7N	GFX2_RX7P	VSS	VDDPCIE	VSS	VDDPCIE	VSS	VDDPCIE	VSS	GPP_REFCLKN
AB	GFX2_TX8N	GFX2_TX8P	VSS	GFX2_RX8N	GFX2_RX8P	VSS	VDDPCIE	VSS	VDDPCIE	VSS	VDDPCIE	VSS	VDDPCIE	VSS
AC	VSS	GFX2_TX9N	GFX2_TX9P	VSS	VSS	VDDPCIE	GFX2_RX13P	VSS	GFX2_RX15P	VSS	GPP_RX9N	VSS	GPP_RX7N	VSS
AD	GFX2_RX9N	GFX2_RX9P	VSS	VSS	VDDPCIE	GFX2_RX12P	GFX2_RX13N	GFX2_RX14P	GFX2_RX15N	PCE_RCALRN	GPP_RX9P	GPP_RX8N	GPP_RX7P	GPP_RX6N
AE	VSS	GFX2_TX10N	GFX2_TX10P	VDDPCIE	VSS	GFX2_RX12N	VSS	GFX2_RX14N	VSS	PCE_RCALRP	VSS	GPP_RX8P	VSS	GPP_RX6P
AF	GFX2_RX10N	GFX2_RX10P	VDDPCIE	VSS	GFX2_RX11P	VSS	GFX2_TX13P	VSS	GFX2_TX15P	VSS	GPP_TX8N	VSS	GPP_TX6N	VSS
AG		VDDPCIE	VSS	GFX2_TX11P	GFX2_RX11N	GFX2_TX12P	GFX2_TX13N	GFX2_TX14P	GFX2_TX15N	GPP_TX9N	GPP_TX8P	GPP_TX7N	GPP_TX6P	GPP_TX5N
AH			VSS	GFX2_TX11N	VSS	GFX2_TX12N	VSS	GFX2_TX14N	VSS	GPP_TX9P	VSS	GPP_TX7P	VSS	GPP_TX5P
	1	2	3	4	5	6	7	8	9	10	11	12	13	14

- CPU Interface
- A-Link Express III Interface
- Clock Interface
- PCIe® External Graphics 0 Interface
- PCIe External Graphics 2 Interface
- PCIe General Purpose Interface
- Power Management Interface
- Core Power
- PCIe Main I/O Power
- PCIe 1.8V I/O Power and PLL Power
- GPIO 1.8V I/O Power
- HyperTransport™ Interface Power
- Grounds
- Other

15	16	17	18	19	20	21	22	23	24	25	26	27	28	
PWM_GPIO4	VSS	POWERGOOD	VDD18	TESTMODE	VSS	DBG_GPIO3	VSS	DFT_GPIO5	VSS	DFT_GPIO1	VSS			A
PWM_GPIO2	PWM_GPIO6	OSCIN	VDD18	PCIE_RESET_GPIO1	I2C_CLK	DBG_GPIO2	DBG_GPIO1	DFT_GPIO4	DFT_GPIO2	DFT_GPIO3	DFT_GPIO0	VSS		B
VSS	PWM_GPIO5	VSS	VDD18	VSS	I2C_DATA	VSS	DBG_GPIO0	VSS	VDDHTTX	VDDHTTX	VDDHTTX	VDDHTTX	VDDHTTX	C
SYSRESET#	VSS	PCIE_RESET_GPIO2	VDD18	PCIE_RESET_GPIO3	VSS	ALLOW_LDTSTOP	VDDHTTX	VDDHTTX	HT_RXCALN	HT_RXCALP	VSS	HT_TXCALN	HT_TXCALP	D
LDTSTOP#	PWM_GPIO1	PCIE_RESET_GPIO5	VDD18	PCIE_RESET_GPIO4	VSS	STRP_DATA	VDDHTTX	HT_TXCAD8P	HT_TXCAD8N	VSS	HT_TXCAD0P	HT_TXCAD0N	VSS	E
VSS	PWM_GPIO3	VSS	VSS	VSS	VSS	VSS	VDDHTTX	VSS	HT_TXCAD9P	HT_TXCAD9N	VSS	HT_TXCAD1P	HT_TXCAD1N	F
VSS	VSS	VSS	VSS	VSS	VSS	VDDA18HTPLL	VDDHTTX	HT_TXCAD10P	HT_TXCAD10N	VSS	HT_TXCAD2P	HT_TXCAD2N	VSS	G
VSS	VSS	VSS	VSS	VSS	VSS	VSS	VDDHTTX	VSS	HT_TXCAD11P	HT_TXCAD11N	VSS	HT_TXCAD3P	HT_TXCAD3N	H
						HT_REFCLKN	VSS	HT_TXCLK1P	HT_TXCLK1N	VSS	HT_TXCLK0P	HT_TXCLK0N	VSS	J
						HT_REFCLKP	VDDHT	VSS	HT_TXCAD12P	HT_TXCAD12N	VSS	HT_TXCAD4P	HT_TXCAD4N	K
VSS	VDDC	VSS	VSS			VDDHT	VSS	HT_TXCAD13P	HT_TXCAD13N	VSS	HT_TXCAD5P	HT_TXCAD5N	VSS	L
VDDC	VSS	VSS	VSS			VSS	VDDHT	VSS	HT_TXCAD14P	HT_TXCAD14N	VSS	HT_TXCAD6P	HT_TXCAD6N	M
VSS	VDDC	VSS	VSS			VDDHT	VSS	HT_TXCAD15P	HT_TXCAD15N	VSS	HT_TXCAD7P	HT_TXCAD7N	VSS	N
VDDC	VSS	VDDC	VSS			VSS	VDDHT	VSS	HT_TXCTL1P	HT_TXCTL1N	VSS	HT_TXCTL0P	HT_TXCTL0N	P
VSS	VDDC	VSS	VSS			VDDHT	VSS	HT_RXCTL1N	HT_RXCTL1P	VSS	HT_RXCTL0N	HT_RXCTL0P	VSS	R
VDDC	VSS	VDDC	VSS			VSS	VDDHT	VSS	HT_RXCAD15N	HT_RXCAD15P	VSS	HT_RXCAD7N	HT_RXCAD7P	T
VSS	VDDC	VSS	VSS			VDDHT	VSS	HT_RXCAD14N	HT_RXCAD14P	VSS	HT_RXCAD6N	HT_RXCAD6P	VSS	U
VSS	VSS	VSS	VDDA18PCIE			VSS	VDDHT	VSS	HT_RXCAD13N	HT_RXCAD13P	VSS	HT_RXCAD5N	HT_RXCAD5P	V
						VDDHT	VSS	HT_RXCAD12N	HT_RXCAD12P	VSS	HT_RXCAD4N	HT_RXCAD4P	VSS	W
						THERMAL DIODE_P	VDDHT	VSS	HT_RXCLK1N	HT_RXCLK1P	VSS	HT_RXCLK0N	HT_RXCLK0P	Y
GPP_REFCLKP	VDDPCIE	VSS	VDDPCIE	VSS	VSS	THERMAL DIODE_N	VDDHT	HT_RXCAD11N	HT_RXCAD11P	VSS	HT_RXCAD3N	HT_RXCAD3P	VSS	AA
VDDPCIE	VSS	VDDPCIE	VSS	VDDPCIE	VSS	VSS	VDDHT	VSS	HT_RXCAD10N	HT_RXCAD10P	VSS	HT_RXCAD2N	HT_RXCAD2P	AB
GPP_RX5N	VSS	GPP_RX3N	VSS	GPP_RX1N	VSS	SB_RX3P	VDDHT	HT_RXCAD9N	HT_RXCAD9P	VSS	HT_RXCAD1N	HT_RXCAD1P	VSS	AC
GPP_RX5P	GPP_RX4N	GPP_RX3P	GPP_RX2N	GPP_RX1P	PCE_BCALRN	SB_RX3N	SB_RX2P	VDDHT	HT_RXCAD8N	HT_RXCAD8P	VSS	HT_RXCAD0N	HT_RXCAD0P	AD
VSS	GPP_RX4P	VSS	GPP_RX2P	VSS	PCE_BCALRP	VSS	SB_RX2N	VSS	VDDHT	VDDHT	VDDHT	VDDHT	VDDHT	AE
GPP_TX4N	VSS	GPP_TX2N	VSS	GPP_TX0N	VSS	SB_TX2P	VSS	SB_TX1P	VSS	SB_RX1P	VSS	VDDHT	VSS	AF
GPP_TX4P	GPP_TX3N	GPP_TX2P	GPP_TX1N	GPP_TX0P	GPP_RX0N	SB_TX2N	SB_TX3P	SB_TX1N	SB_TX0P	SB_RX1N	SB_RX0P	VSS		AG
VSS	GPP_TX3P	VSS	GPP_TX1P	VSS	GPP_RX0P	VSS	SB_TX3N	VSS	SB_TX0N	VSS	SB_RX0N			AH
15	16	17	18	19	20	21	22	23	24	25	26	27	28	

- CPU Interface
- A-Link Express III Interface
- Clock Interface
- PCIe External Graphics 0 Interface
- PCIe External Graphics 2 Interface
- PCIe General Purpose Interface
- Power Management Interface
- Core Power
- PCIe Main I/O Power
- PCIe 1.8V I/O Power and PLL Power
- GPIO 1.8V I/O Power
- HyperTransport Interface Power
- Grounds
- Other

3.2 RD890 Interface Block Diagram

Figure 3-1 shows the different interfaces on the RD890. Interface names in blue are hyperlinks to the corresponding sections in this chapter.

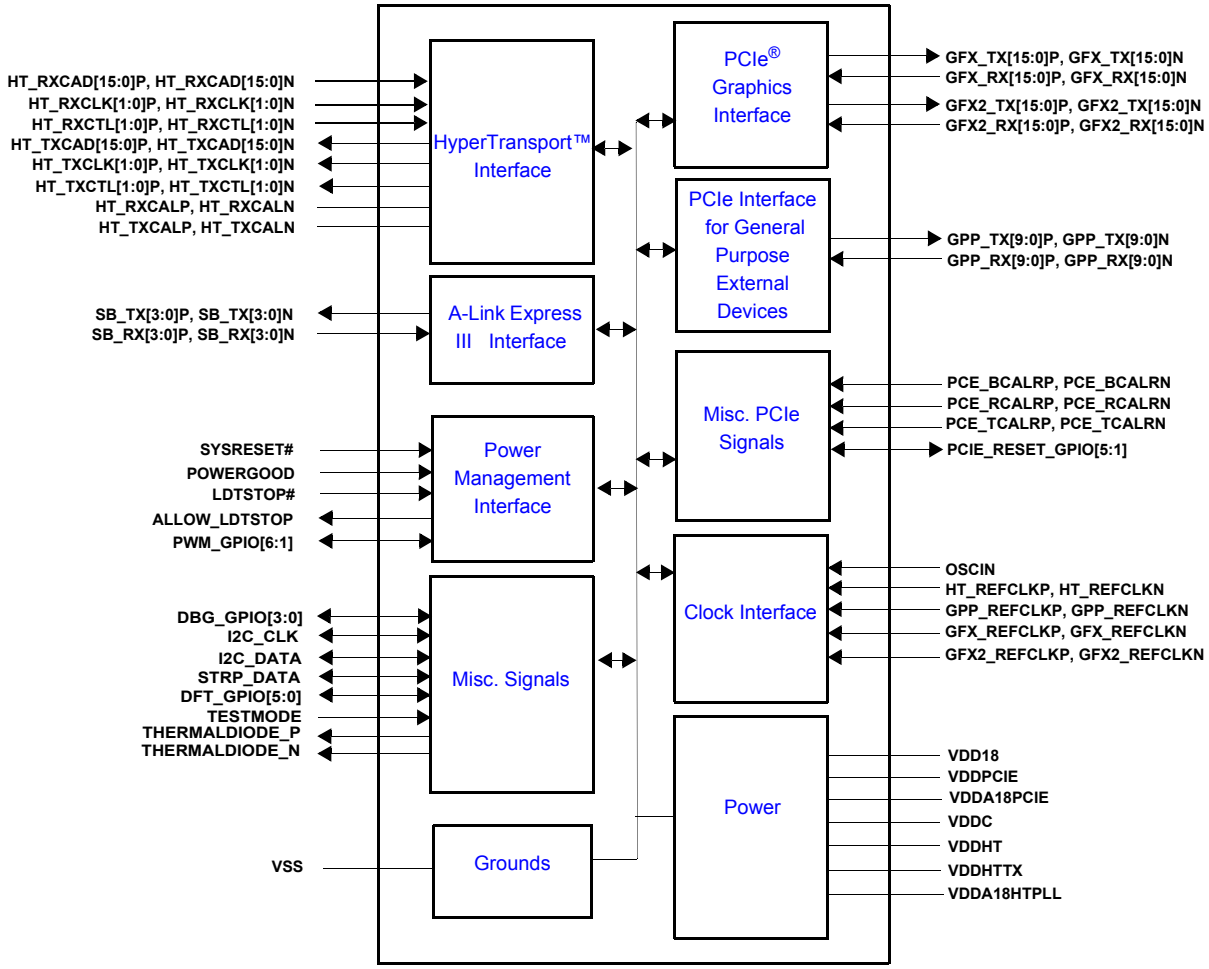

Figure 3-1 RD890 Interface Block Diagram

3.3 CPU HyperTransport™ Interface

Table 3-1 HyperTransport™ Interface

Pin Name	Type	Power Domain	Ground Domain	Functional Description
HT_RXCAD[15:0]P, HT_RXCAD[15:0]N	I	VDDHT	VSS	Receiver Command, Address, and Data Differential Pairs
HT_RXCLK[1:0]P, HT_RXCLK[1:0]N	I	VDDHT	VSS	Receiver Clock Signal Differential Pair. Forwarded clock signal. Each byte of RXCAD uses a separate clock signal. Data is transferred on each clock edge.
HT_RXCTL[1:0]P, HT_RXCTL[1:0]N	I	VDDHT	VSS	Receiver Control Differential Pair. The pair is for distinguishing control packets from data packets. Each byte of RXCAD uses a separate control signal.
HT_TXCAD[15:0]P, HT_TXCAD[15:0]N	O	VDDHT	VSS	Transmitter Command, Address, and Data Differential Pairs

Table 3-1 HyperTransport™ Interface (Continued)

Pin Name	Type	Power Domain	Ground Domain	Functional Description
HT_TXCLK[1:0]P, HT_TXCLK[1:0]N	O	VDDHT	VSS	Transmitter Clock Signal Differential Pair. Forwarded clock signal. Each byte of TXCAD uses a separate clock signal. Data is transferred on each clock edge.
HT_TXCTL[1:0]P, HT_TXCTL[1:0]N	O	VDDHT	VSS	Transmitter Control Differential Pair. The pair is for distinguishing control packets from data packets. Each byte of TXCAD uses a separate control signal.
HT_RXCALN	Other	VDDHT	VSS	Receiver Calibration Resistor to HT_RXCALP
HT_RXCALP	Other	VDDHT	VSS	Receiver Calibration Resistor to HT_RXCALN
HT_TXCALP	Other	VDDHT	VSS	Transmitter Calibration Resistor to HTTX_CALN
HT_TXCALN	Other	VDDHT	VSS	Transmitter Calibration Resistor to HTTX_CALP

3.4 PCI Express® Interfaces

3.4.1 Interface for External Graphics Controllers

Table 3-2 2 x 16 or 4 x 8 PCI Express® Interface for External Graphics

Pin Name	Type	Power Domain	Ground Domain	Integrated Termination	Functional Description
GFX_TX[15:0]P, GFX_TX[15:0]N	O	VDDA18PCIE	VSSA_PCIE	50Ω between complements	External Graphics 0 Transmit Data Differential Pairs. Connect to connector[s] for external graphics card[s] on the motherboard.
GFX_RX[15:0]P, GFX_RX[15:0]N	I	VDDA18PCIE	VSSA_PCIE	50Ω between complements	External Graphics 0 Receive Data Differential Pairs. Connect to connector[s] for external graphics card[s] on the motherboard.
GFX2_TX[15:0]P, GFX2_TX[15:0]N	O	VDDA18PCIE	VSSA_PCIE	50Ω between complements	External Graphics 2 Transmit Data Differential Pairs. Connect to connector[s] for external graphics card[s] on the motherboard.
GFX2_RX[15:0]P, GFX2_RX[15:0]N	I	VDDA18PCIE	VSSA_PCIE	50Ω between complements	External Graphics 2 Receive Data Differential Pairs. Connect to connector[s] for external graphics card[s] on the motherboard.

3.4.2 Interface for General Purpose External Devices

Table 3-3 PCI Express® Interface for General Purpose External Devices

Pin Name	Type	Power Domain	Ground Domain	Integrated Termination	Functional Description
GPP_TX[9:0]P, GPP_TX[9:0]N	O	VDDA18PCIE	VSSA_PCIE	50Ω between complements	General Purpose Transmit Data Differential Pair for general purpose external devices. Connect to an external connector on the motherboard for ExpressCard support.
GPP_RX[9:0]P, GPP_RX[9:0]N	I	VDDA18PCIE	VSSA_PCIE	50Ω between complements	General Purpose Receive Data Differential Pair for general purpose external devices. Connect to an external connector on the motherboard for ExpressCard support.

3.4.3 A-Link Express III Interface to Southbridge

Table 3-4 1 x 4 Lane A-Link Express III Interface for Southbridge

Pin Name	Type	Power Domain	Ground Domain	Integrated Termination	Functional Description
SB_TX[3:0]P, SB_TX[3:0]N	O	VDDA18PCIE	VSSA_PCIE	50Ω between complements	Southbridge Transmit Data Differential Pairs. Connect to the corresponding Receive Data Differential Pairs on the Southbridge.
SB_RX[3:0]P, SB_RX[3:0]N	I	VDDA18PCIE	VSSA_PCIE	50Ω between complements	Southbridge Receive Data Differential Pairs. Connect to the corresponding Transmit Data Differential Pairs on the Southbridge.

3.4.4 Miscellaneous PCI Express® Signals

Table 3-5 Miscellaneous PCI Express® Signals

Pin Name	Type	Power Domain	Ground Domain	Functional Description
PCE_BCALRN	I	VDDA18PCIE	VSSA_PCIE	N Channel Driver Compensation Calibration for Rx and Tx Channels on Bottom Side.
PCE_BCALRP	I	VDDA18PCIE	VSSA_PCIE	P Channel Driver Compensation Calibration for Rx and Tx Channels on Bottom Side
PCE_TCALRN	I	VDDA18PCIE	VSSA_PCIE	N Channel Driver Compensation Calibration for Rx and Tx Channels on Top Side.
PCE_TCALRP	I	VDDA18PCIE	VSSA_PCIE	P Channel Driver Compensation Calibration for Rx and Tx Channels on Top Side
PCE_RCALRN	I	VDDA18PCIE	VSSA_PCIE	N Channel Driver Compensation Calibration for Rx and Tx Channels on Right Side.
PCE_RCALRP	I	VDDA18PCIE	VSSA_PCIE	P Channel Driver Compensation Calibration for Rx and Tx Channels on Right Side
PCIE_RESET_GPIO[5:1]	I/O	VDDA18PCIE	VSS	PCIe Resets. Except for PCIE_RESET_GPIO3, they can also be used as GPIOs. There are internal pull-downs of 1.7 kΩ on these pins.

3.5 Clock Interface

Table 3-6 Clock Interface

Pin Name	Type	Power Domain	Ground Domain	Integrated Termination	Functional Description
HT_REFCLKP, HT_REFCLKN	I	VDDA18HTPLL	VSSA_HT	Disabled	HyperTransport™ 100 MHz Clock Differential Pair from external clock source
GFX_REFCLKP, GFX_REFCLKN	I	VDDA18PCIE	VSSA_PCIE	–	External Graphics 0 Clock Differential Pair. The pair is connected to an external clock generator on the motherboard when external graphics controller 0 is used.
GFX2_REFCLKP, GFX2_REFCLKN	I	VDDA18PCIE	VSSA_PCIE	–	External Graphics 2 Clock Differential Pair. The pair is connected to an external clock generator on the motherboard when external graphics controller 2 is used.
GPP_REFCLKP, GPP_REFCLKN	I	VDDA18PCIE	VSSA_PCIE	–	General Purpose Differential Pair. **The pair has to be connected to an external clock generator on the motherboard whether the General Purpose link is used or not.**
OSCIN	I	VDD18	VSS	Disabled	14.318MHz Reference clock input from the external clock chip (1.8 volt signaling)

3.6 Power Management Pins

Table 3-7 Power Management Pins

Pin Name	Type	Power Domain	Ground Domain	Functional Description
ALLOW_LDTSTOP	OD	VDD18	VSS	Allow LDTSTOP. This signal is used by the RD890 to communicate with the Southbridge and tell it when it can assert the LDTSTOP# signal. 1 = LDTSTOP# can be asserted 0 = LDTSTOP# has to be de-asserted
LDTSTOP#	I	VDD18	VSS	HyperTransport™ Stop. This signal is generated by the Southbridge and is used to determine when the HyperTransport link should be disconnected and go into a low-power state. It is a single-ended signal.
POWERGOOD	I	VDD18	VSS	Input from the motherboard signifying that the power to the RD890 is up and ready. Signal High means all power planes are valid. It is not observed internally until it has been high for more than 6 consecutive REFCLK cycles. The rising edge of this signal is deglitched.
PWM_GPIO[6:1]	I/O	VDD18	VSS	PWM generators. PWM_GPIO6 and PWM_GPIO[4:3] are also parts of the test interface (see *section 7.2, "Test Interface," on page 7- 1*). PWM_GPIO[4:2] are also used as strap pins (see *section 3.10, "Strapping Options," on page 3- 10*), and the internal pull-ups on them are automatically disabled when they are used for PWM functionality. Can also be used as GPIOs.
SYSRESET#	I	VDD18	VSS	Global Hardware Reset. This signal comes from the Southbridge.

3.7 Miscellaneous Pins

Table 3-8 Miscellaneous Pins

Pin Name	Type	Power Domain	Ground Domain	Integrated Termination	Functional Description
I2C_CLK	I/O	VDD18	VSS	–	I^2C interface clock signal. Can also be used as GPIO.
I2C_DATA	I/O	VDD18	VSS	–	I^2C interface data signal. Can also be used as GPIO.
STRP_DATA	I/O	VDD18	VSS	–	I^2C interface data signal for external EEPROM based strap loading. See the RD890 Strap Document for details on the operation.
TESTMODE	I	VDD18	VSS	–	When High, puts the RD890 in test mode and disables the RD890 from operating normally.
DFT_GPIO[5:0]	I/O	VDD18	VSS	Pull Up	Outputs for DFT TESTMODE. These pins cannot be used for general GPIO functions.
DBG_GPIO[3:0]	I/O	VDD18	VSS	Pull Up	Outputs for Debug Bus. These pins cannot be used for general GPIO functions.
THERMALDIODE_P, THERMALDIODE_N	A-O	–	–	–	Diode connections to external SM Bus microcontroller for monitoring IC thermal characteristics.

3.8 Power Pins

Table 3-9 Power Pins

Pin Name	Voltage	Pin Count	Ball Reference	Comments
VDDC	1.1V	18	L14, L16, M13, M15, N12, N14, N16, P13, P15, P17, R12, R14, R16, T13, T15, T17, U14, U16	Core power
VDD18	1.8V	5	A18, B18, C18, D18, E18	I/O Power for GPIO pads

Table 3-9 Power Pins (Continued)

Pin Name	Voltage	Pin Count	Ball Reference	Comments
VDDPCIE	1.1 V	39	A3, B2, C1, C3, D4, E5, F6, G8, G10, H7, H9, H11, K7, L8, M7, N8, P7, R8, T7, V7, W8, Y7, AA8, AA10, AA12, AA16, AA18, AB7, AB9, AB11, AB13, AB15, AB17, AB19, AC6, AD5, AE4, AF3, AG2	PCI Express interface main I/O and PLL power
VDDA18PCIE	1.8 V	21	A12, A1, B12, B13, C12, C13, D12, D13, E12, E13, F12, F13, G12, G13, G14, H12, H13, H14, L11, V11, V18	PCI Express interface 1.8V I/O power
VDDHT	1.1V	21	AA22, AB22, AC22, K22, AD23, AE24, AE25, AE26, AE27, AE28, AF27, L21, M22, N21, P22, R21, T22, U21, V22, W21, Y22	HyperTransport™ Interface digital I/O power
VDDHTTX	1.2V	11	C24, C25, C26, C27, C28, D22, D23, E22, F22, G22, H22	HyperTransport Transmit Interface I/O power
VDDA18HTPLL	1.8V	1	G21	HyperTransport interface 1.8V PLL Power
Total Power Pin Count		116		

3.9 Ground Pins

Table 3-10 Ground Pins

Pin Name	Pin Count	Ball Reference	Comments
VSS	261	A11, A14, A16, A20, A22, A24, A26, A5, A7, A9, AA1, AA11, AA13, AA17, AA19, AA20, AA25, AA28, AA4, AA7, AA9, AB10, AB12, AB14, AB16, AB18, AB20, AB21, AB23, AB26, AB3, AB6, AB8, AC1, AC10, AC12, AC14, AC16, AC18, AC20, AC25, AC28, AC4, AC5, AC8, AD26, AD3, AD4, AE1, AE11, AE13, AE15, AE17, AE19, AE21, AE23, AE5, AE7, AE9, AF10, AF12, AF14, AF16, AF18, AF20, AF22, AF24, AF26, AF28, AF4, AF6, AF8, AG27, AG3, AH11, AH13, AH15, AH17, AH19, AH21, AH23, AH25, AH3, AH5, AH7, AH9, B14, B27, B3, C10, C14, C15, C17, C19, C2, C21, C23, C4, C6, C8, D11, D14, D16, D20, D26, D3, D5, D7, D9, E1, E20, E25, E28, E4, F10, F15, F17, F18, F19, F20, F21, F23, F26, F3, F8, G1, G11, G15, G16, G17, G18, G19, G20, G25, G28, G4, G9, H10, H15, H16, H17, H18, H19, H20, H21, H23, H26, H3, H6, J1, J22, J25, J28, J4, J7, K23, K26, K3, K6, K8, L1, L12, L13, L15, L17, L18, L22, L25, L28, L4, L7, M11, M12, M14, M16, M17, M18, M21, M23, M26, M3, M6, M8,N1 N11, N13, N15, N17, N18, N22, N25, N28, N4, N7, P11, P12, P14, P16, P18, P21, P23, P26, P3, P6, P8, R1, R11, R13, R15, R17, R18, R22, 25, R28, R4, R7, T11, T12, T14, T16, T18, T21, T23, T26, T3, T6, T8, U1, U11, U12, U13, U15, U17, U18, U22, U25, U28, U4, U7, V12, V13, V14, V15, V16, V17, V21, V23, V26, V3, V6, W1, W22, W25, W28, W4, W7, Y23, Y26, Y3, Y6, Y8	Common Ground

3.10 Strapping Options

The RD890 provides strapping options to define specific operating parameters. The strap values are latched into internal registers after the assertion of the POWERGOOD signal to the RD890. *Table 3-11, "Strap Definitions for the RD890,"* shows the definitions of all the strap functions. These straps are set by one of the following four methods:

- Allowing the internal pull-up resistors to set all strap values "1"'s automatically.
- Attaching pull-down resistors to specific strap pins listed in *Table 3-11* to set their values to "0"'s.
- Downloading the strap values from an I^2C serial EEPROM (for debug purpose only; contact your AMD FAE representative for details).
- Setting through an external debug port, if implemented (contact your AMD FAE representative for details).

Table 3-11 Strap Definitions for the RD890

Strap Function	Strap Pin	Description
Reserved	PWM_GPIO[5:2]	Reserved. Make provision for an external pull-down resistor on each of the pins, but do not install a resistor.
Reserved	DFT_GPIO0	Reserved. Make provision for an external pull-down resistor on this pin, but do not install a resistor.
LOAD_ROM_STRAPS#	DFT_GPIO1	Selects loading of strap values from EEPROM 0: I^2C master can load strap values from EEPROM if connected, or use hardware default values if not connected **1: Use hardware default values (Default)**
STRAP_PCIE_GPP_CFG	DFT_GPIO[4:2]	General Purpose Link Configuration. See *Table 3-12* below for details.
Reserved	DFT_GPIO5	Reserved. Make provision for an external pull-down resistor on this pin, but do not install a resistor.

Table 3-12 Strap Definition for STRAP_PCIE_GPP_CFG

Strap Pin Value			Link Width										Mode
DFT_GPIO4	DFT_GPIO3	DFT_GPIO2	GPP0	GPP1	GPP2	GPP3	GPP4	GPP5	GPP6	GPP7	GPP8	GPP9	
1	**1**	**1**	**Hardware default (Mode L) or EEPROM strap values (Default)**										**-**
1	1	0	Hardware default (Mode L) or EEPROM strap values										-
1	0	1	x2		x2		x2		x4				C2
1	0	0	x2		x2		x1	x1	x4				K
0	1	1	x2		x1	x1	x1	x1	x4				E
0	1	0	x1	x1	x1	x1	x1	x1	x4				L (Hardware Default)
0	0	1	x4				x1	x1	x4				C
0	0	0	x4				x2		x4				B

Note: If the pin straps instead of strap values from EEPROM are used, the GPP configuration will then be determined according to this table and cannot be changed after the system has been powered up.

Chapter 4
Timing Specifications

4.1 HyperTransport™ Bus Timing

For HyperTransport™ bus timing information, please refer to specifications by AMD.

4.2 PCI Express® Differential Clock AC Specifications

Table 4-1 Timing Requirements for PCIe® Differential Clocks (GFX_REFCLK, GFX2_REFCLK, and GPP_REFCLK at 100MHz)

Symbol	Description	Minimum	Maximum	Unit
Rising Edge Rate	Rising Edge Rate	0.6	4.0	V/ns
Falling Edge Rate	Falling Edge Rate	0.6	4.0	V/ns
$T_{PERIOD\ AVG}$	Average Clock Period Accuracy	-300	+2800	ppm
$T_{PERIOD\ ABS}$	Absolute Period (including jitter and spread spectrum modulation)	9.847	10.203	ns
$T_{CCJITTER}$	Cycle to Cycle Jitter	-	150	ps
Duty Cycle	Duty Cycle	40	60	%
Rise-Fall Matching	Rising edge rate (REFCLK+) to falling edge rate (REFCLK-) matching	-	20	%

4.3 HyperTransport™ Reference Clock Timing Parameters

Table 4-2 Timing Requirements for HyperTransport™ Reference Clock (100MHz)

Symbol	Parameter	Minimum	Maximum	Unit	Note
ΔV_{CROSS}	Change in Crossing point voltage over all edges	-	140	mV	1
F	Frequency	99.5	100	MHz	2
ppm	Long Term Accuracy	-300	+300	ppm	3
S_{FALL}	Output falling edge slew rate	-10	-0.5	V/ns	4, 5
S_{RISE}	Output rising edge slew rate	0.5	10	V/ns	4,5
$T_{jc\ max}$	Jitter, cycle to cycle	-	150	ps	6
$T_{j\text{-}accumulated}$	Accumulated jitter over a 10 μs period	-1	1	ns	7
$V_{D(PK\text{-}PK)}$	Peak to Peak Differential Voltage	400	2400	mV	8
V_D	Differential Voltage	200	1200	mV	9
ΔV_D	Change in V_{DDC} cycle to cycle	-75	75	mV	10

Table 4-2 Timing Requirements for HyperTransport™ Reference Clock (100MHz) (Continued)

Symbol	Parameter	Minimum	Maximum	Unit	Note
DC	Duty Cycle	45	55	%	11

Notes:
More details are available in *AMD HyperTransport 3.0 Reference Clock Specification* and *AMD Family 10h Processor Reference Clock Parameters*, document # 34864
1 Single-ended measurement at crossing point. Value is maximum-minimum over all time. DC Value of common mode is not important due to blocking cap.
2 Minimum frequency is a consequence of 0.5% down spread spectrum.
3 Measured with spread spectrum turned off.
4 Only simulated at the receive die pad. This parameter is intended to give guidance for simulation. It cannot be tested on a tester but is guaranteed by design.
5 Differential measurement through the range of ±100mV, differential signal must remain monotonic and within slew rate specification when crossing through this region.
6 $T_{jc\ max}$ is the maximum difference of t_{CYCLE} between any two adjacent cycles.
7 Accumulated T_{jc} over a 10µs time period, measured with JIT2 TIE at 50ps interval.
8 $V_{D(PK-PK)}$ is the overall magnitude of the differential signal.
9 $V_{D(min)}$ is the amplitude of the ring-back differential measurement, guaranteed by design that the ring-back will not cross 0V V_D. $V_{D(max)}$ is the largest amplitude allowed.
10 The difference in magnitude of two adjacent V_{DDC} measurements. V_{DDC} is the stable post overshoot and ring-back part of the signal.
11 Defined as t_{HIGH}/t_{CYCLE}

4.4 OSCIN Reference Clock Timing Parameters

Table 4-3 Timing Requirements for OSCIN Reference Clock (14.3181818MHz)

Symbol	Parameter	Min	Typical	Max	Unit	Note
TIP	REFCLK Period	0.037	–	1.1	µs	1
FIP	REFCLK Frequency	0.9	–	27	MHz	2
TIH	REFCLK High Time	2.0	–	–	ns	
TIL	REFCLK Low Time	2.0	–	–	ns	
TIR	REFCLK Rise Time	–	–	1.5	ns	
TIF	REFCLK Fall Time	–	–	1.5	ns	
TIJCC	REFCLK Cycle-to-Cycle Jitter Requirement	–	–	200	ps	
TIJPP	REFCLK Peak-to-Peak Jitter Requirement	–	–	200	ps	1
TIJLT	REFCLK Long Term Jitter Requirement (1µs after scope trigger)	–	–	500	ps	

Notes:
1 Time intervals measured at 50% threshold point.
2 FIP is the reciprocal of TIP.

4.5 Power Rail Sequence

For the purpose of power rail sequencing, the power rails of the RD890 are divided into groupings described in Table 4-4 below.

Table 4-4 Power Rail Groupings for the RD890

Group Name	Power rail name	Voltage	ACPI STATE	Description
VDDC	VDDC	1.1V	S0-S2	Core power
VDDPCIE	VDDPCIE	1.1V	S0-S2	PCI Express® main IO power
VDDHTTX	VDDHTTX	1.2V	S0-S2	HyperTransport™ transmit interface IO power
HT_1.1V	VDDHT	1.1V	S0-S2	HyperTransport interface digital IO power

Table 4-4 Power Rail Groupings for the RD890

Group Name	Power rail name	Voltage	ACPI STATE	Description
1.8V	VDD18	1.8V	S0-S2	I/O power for GPIO pads
	VDDA18PCIE	1.8V	S0-S2	PCI Express interface 1.8V IO and PLL power
	VDDA18HTPLL	1.8V	S0-S2	HyperTransport interface 1.8V PLL power

Note:
1. Power rails from the same group are assumed to be generated by the same voltage regulator.
2. Power rails from different groups but at the same voltage can either be generated by separate regulators or by the same regulators as long as they comply with the requirements specified in the *RD890 Motherboard Design Guide*.

4.5.1 Power Up

Figure 4-1 below illustrates the power up sequencing for the various power groups, and Table 4-5 explains the symbols in the figure, as well as the associated requirements.

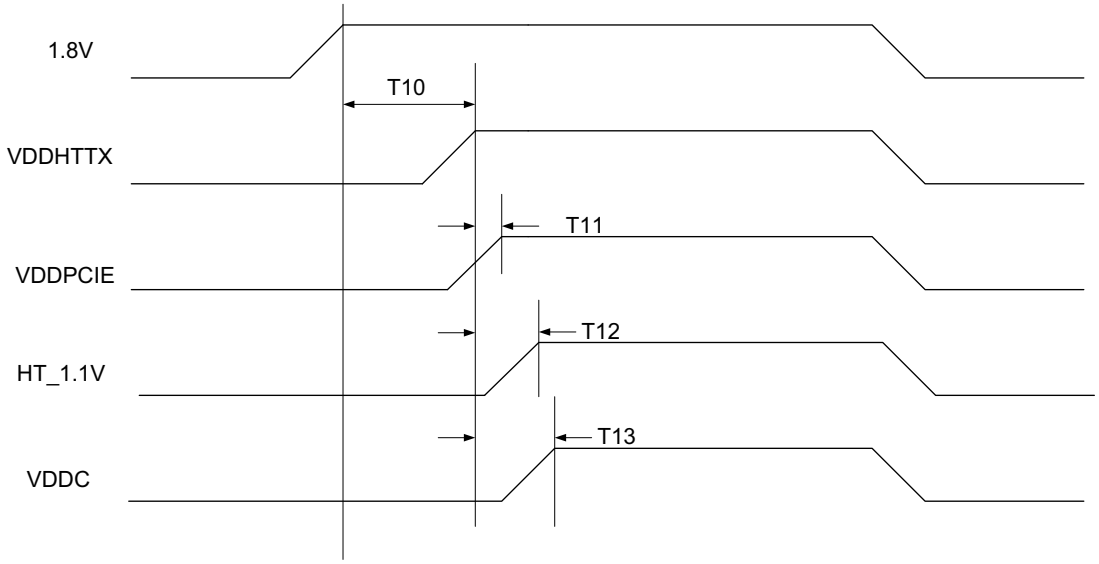

Figure 4-1 RD890 Power Rail Power Up Sequence

Table 4-5 RD890 Power Rail Power-up Sequence

Symbol	Parameter	Requirement	Comment
T10	1.8V rails to VDDHTTX (1.2V)	VDDHTTX ramps after 1.8V rails.	See Note 1.
T11	VDDHTTX (1.2V) to VDDPCIE (1.1V)	VDDPCIE ramps together with or after VDDHTTX	See Note 1 and 2.
T12	VDDHTTX(1.2V) to HT_1.1V rails	HT_1.1V rails ramp together with or after VDDHTTX	See Note 1 and 2.
T13	VDDHTTX(1.2V) to VDDC (1.1V)	VDDC ramps together with or after VDDHTTX	See Note 1 and 2.

Notes:
1. Power rail A ramps after power rail B means that the voltage of rail A does not exceed that of rail B at any time.
2. Power rail A ramps together with power rail B means that the two rails are controlled by the same enable signal and the difference in their ramping rates is only due to the differences in the loadings.

4.5.2 Power Down

For power down, the rails should either be turned off simultaneously or in the reversed order of the power up sequence. Variations in speeds of decay due to different capacitor discharge rates can be safely ignored.

Chapter 5
Electrical Characteristics and Physical Data

5.1 Electrical Characteristics

5.1.1 Maximum and Minimum Ratings

Table 5-1 Power Rail Maximum and Minimum Voltage Ratings

Pin	Typical	DC Limit*		AC Limit*		Unit	Comments
		Min.	Max.	Min.	Max.		
VDDC	1.1	1.067	1.133	1.045	1.155	V	Core power
VDD18	1.8	1.746	1.854	1.71	1.89	V	1.8V I/O Powers
VDDPCIE	1.1	1.067	1.133	1.045	1.155	V	PCI Express® Interface Main I/O Power
VDDA18PCIE	1.8	1.746	1.854	1.71	1.89	V	PCI Express interface 1.8V I/O and PLL power
VDDHT	1.1	1.067	1.133	1.045	1.155	V	HyperTransport™ Interface digital I/O power
VDDHTTX	1.2	1.164	1.236	1.14	1.26	V	HyperTransport Transmit Interface I/O power
VDDA18HTPLL	1.8	1.746	1.854	1.71	1.89	V	HyperTransport interface 1.8V PLL power

*** Note:** The voltage set-point must be contained within the DC specification in order to ensure proper operation. Voltage ripple and transient events outside the DC specification must remain within the AC specification at all times. Transients must return to within the DC specification within 20µs.

5.1.2 DC Characteristics

Table 5-1 DC Characteristics for PCIe® Differential Clocks (GFX_REFCLK, GFX2_REFCLK, and GPP_REFCLK at 100MHz)

Symbol	Description	Minimum	Maximum	Unit
V_{IL}	Differential Input Low Voltage	-	-150	mV
V_{IH}	Differential Input High Voltage	+150	-	mV
V_{CROSS}	Absolute Crossing Point Voltage	+250	+550	mV
$V_{CROSS\ DELTA}$	Variation of V_{CROSS} over all rising clock edges	-	+140	mV
V_{RB}	Ring-back Voltage Margin	-100	+100	mV
V_{IMAX}	Absolute Max Input Voltage	-	+1.15	V
V_{IMIN}	Absolute Min Input Voltage	-	-0.15	V

Table 5-2 DC Characteristics for 1.8V GPIO Pads

Symbol	Description	Minimum	Maximum	Unit	Notes
V_{IH-DC}	Input High Voltage	1.1	-	V	1
V_{IL-DC}	Input Low Voltage	-	0.7	V	1
V_{OH}	Minimum Output High Voltage @ I=8mA	1.4	-	V	2, 3
V_{OL}	Maximum Output Low Voltage @ I=8mA	-	0.4	V	2, 3
I_{OL}	Minimum Output Low Current @ V=0.1V	2.0	-	mA	2, 3

Table 5-2 DC Characteristics for 1.8V GPIO Pads

Symbol	Description	Minimum	Maximum	Unit	Notes
I_{OH}	Minimum Output High Current @ V=VDDR-0.1V	2.0	-	mA	2, 3

Notes:
1) Measured with edge rate of 1us at PAD pin.
2) For detailed current/voltage characteristics please refer to IBIS model.
3) Measurement taken with SP/SN set to default values, PVT=Noml Case

Table 5-3 DC Characteristics for the HyperTransport™ 100MHz Differential Clock (HT_REFCLK)

Symbol	Description	Minimum	Typical	Maximum	Comments
V_{IL}	Input Low Voltage	–	0V	0.2V	–
V_{IH}	Input High Voltage	1.4V	1.8V	–	–
V_{IMAX}	Maximum Input Voltage	–	–	2.1V	–

5.2 RD890 Thermal Characteristics

This section describes some key thermal parameters of the RD890. For a detailed discussion on these parameters and other thermal design descriptions, including package level thermal data and analysis, please consult the *Thermal Design and Analysis Guidelines for RD890*.

5.2.1 RD890 Thermal Limits

Table 5-4 RD890 Thermal Limits

Parameter	Minimum	Nominal	Maximum	Unit	Note
Operating Case Temperature	0	—	95	°C	1
Absolute Rated Junction Temperature	—	—	115	°C	2
Storage Temperature	-40	—	60	°C	
Ambient Temperature	0	—	45	°C	3
Thermal Design Power	—	19.6	—	W	4

Notes:
1 - The maximum operating case temperature is the die top-center temperature measured via a thermocouple based on the methodology given in the document *Thermal Design and Analysis Guidelines for RD890* (Chapter 12). This is the temperature at which the functionality of the chip is qualified.
2 - The maximum absolute rated junction temperature is the junction temperature at which the device can operate without causing damage to the ASIC.
3 - The ambient temperature is defined as the temperature of the local intake air at the inlet to the thermal management device. The maximum ambient temperature is dependent on the heat sink design, and the value given here is based on AMD's reference heat sink solution for the RD890. Refer to Chapter 6 in *Thermal Design and Analysis Guidelines for RD890* for heatsink and thermal design guidelines. Refer to Chapter 7 for details of ambient conditions.
4 - Thermal Design Power (TDP) is defined as the highest power dissipated while running currently available worst case applications at nominal voltages. The core voltage was raised to 5% above its nominal value for measuring the ASIC power. Since the core power of modern ASICs using 65nm and smaller process technology can vary significantly, parts specifically screened for higher core power were used for TDP measurement. The TDP is intended only as a design reference, and the value given here is preliminary.

5.2.2 Thermal Diode Characteristics

The RD890 has an on-die thermal diode, with its positive and negative terminals connected to the THERMALDIODE_P and THERMALDIODE_N pins respectively. Combined with a thermal sensor circuit, the diode temperature, and hence the ASIC junction temperature, can be derived from a differential voltage reading (ΔV). The equation relating the temperature to ΔV is given below.

$$\Delta V = \frac{\eta \times K \times T \times \ln(N)}{q}$$

where:

ΔV = Difference of two base-to-emitter voltage readings, one using current = I and the other using current = N x I

N = Ratio of the two thermal diode currents (=10 when using an ADI thermal sensor, e.g.: ADM 1020, 1030)

η = Ideality factor of the diode

K = Boltzman's Constant

T = Temperature in Kelvin

q = Electron charge

The series resistance of the thermal diode (R_T) must be taken into account as it introduces an error in the reading (for every 1.0Ω, approximately 0.8°C is added to the reading). The sensor circuit should be calibrated to offset the R_T induced, plus any other known fixed errors. Measured values of diode ideality factor and series resistance for the diode circuit are defined in *Thermal Design and Analysis Guidelines for RD890*.

5.3 Package Information

Figure 5-2 and *Table 5-5* describe the physical dimensions of the RD890 package. *Figure 5-3* shows the detailed ball arrangement for the RD890.

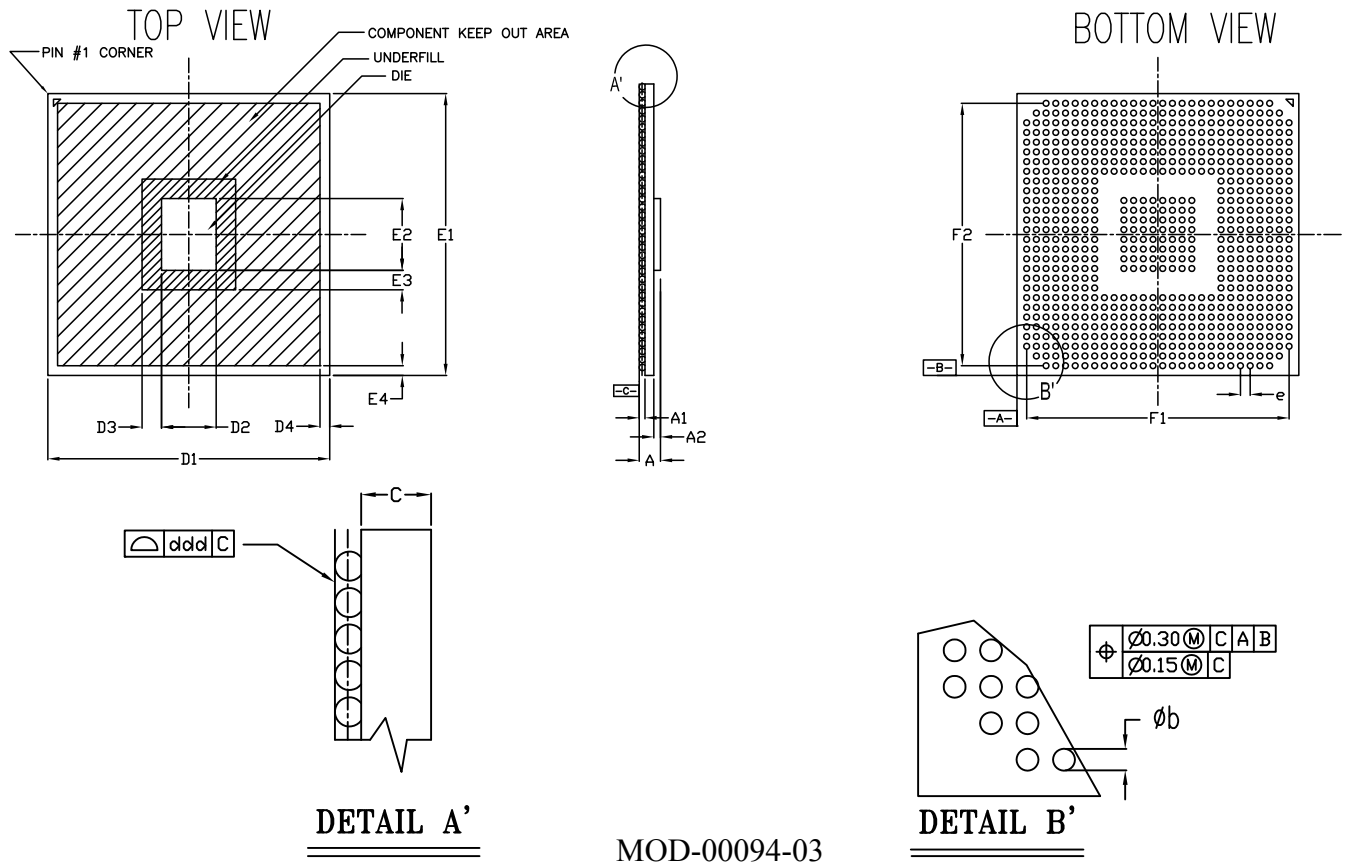

Figure 5-2 RD890 692-Pin FCBGA Package Outline

Table 5-5 RD890 692-Pin FCBGA Package Physical Dimensions

Ref.	Min. (mm)	Typical (mm)	Max. (mm)
c	0.56	0.66	0.76
A	1.87	2.02	2.17
A1	0.40	0.50	0.60
A2	0.81	0.86	0.91
ϕb	0.50	0.60	0.70
D1	28.80	29.00	29.20
D2	-	5.62	-
D3	2.00	-	-
D4	1.00	-	-
E1	28.80	29.00	29.20
E2	-	7.39	-
E3	2.00	-	-
E4	1.00	-	-
F1	-	27.00	-
F2	-	27.00	-
e	-	1.00	-

Table 5-5 RD890 692-Pin FCBGA Package Physical Dimensions

Ref.	Min. (mm)	Typical (mm)	Max. (mm)
ddd	-	-	0.20

Note: Maximum height of SMT components is 0.650 mm.

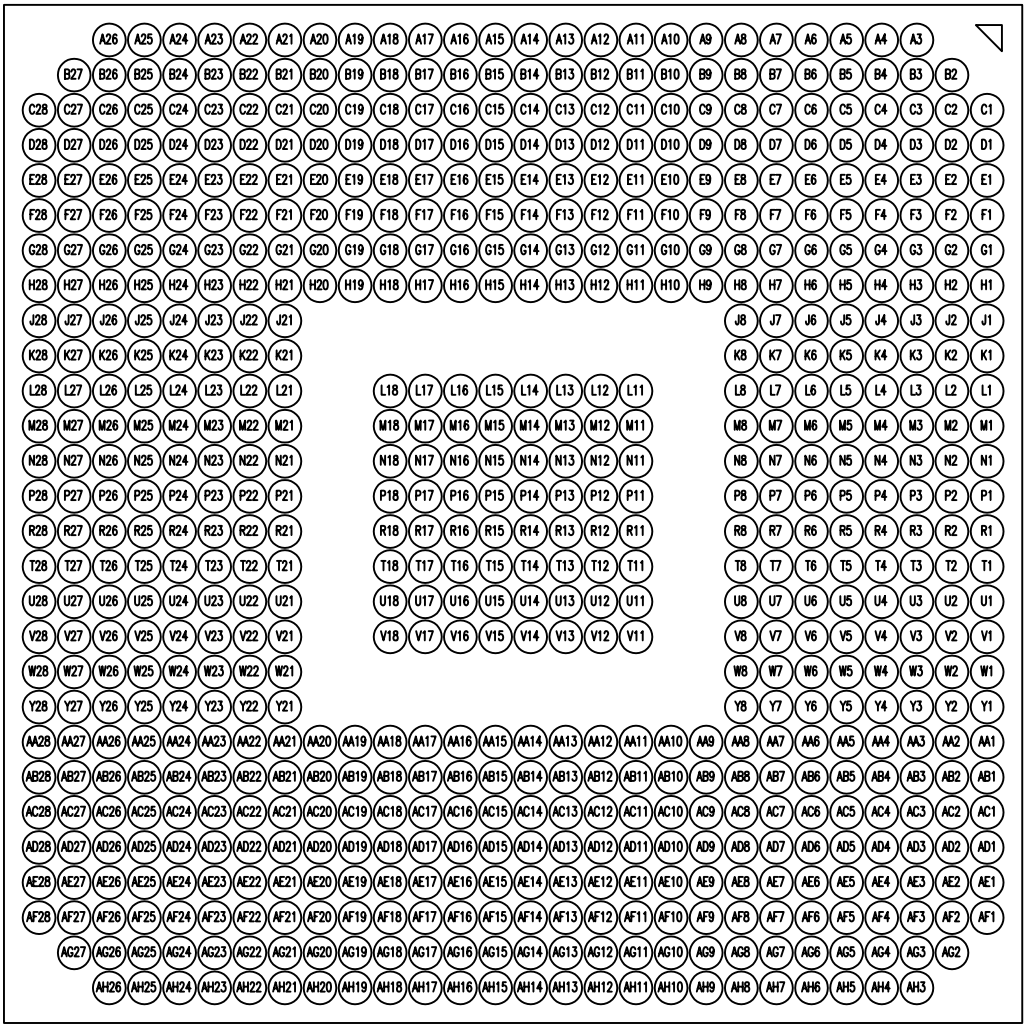

Figure 5-3 RD890 Ball Arrangement (Bottom View)

5.3.1 Pressure Specification

To avoid damages to the ASIC (die or solder ball joint cracks) caused by improper mechanical assembly of the cooling device, follow the recommendations below:

- It is recommended that the maximum load that is evenly applied across the contact area between the thermal management device and the die does not exceed 6 lbf. Note that a total load of 4-6 lbf is adequate to secure the thermal management device and achieve the lowest thermal contact resistance with a temperature drop across the thermal interface material of no more than 3°C. Also, the surface flatness of the metal spreader should be 0.001 inch/1 inch.
- Pre-test the assembly fixture with a strain gauge to make sure that the flexing of the final assembled board and the pressure applied around the ASIC package will not exceed 600 micronstrains under any circumstances.

- Ensure that any distortion (bow or twist) of the board after SMT and cooling device assembly is within industry guidelines (IPC/EIA J-STD-001). For measurement method, refer to the industry approved technique described in the manual IPC-TM-650, section 2.4.22.

5.3.2 Board Solder Reflow Process Recommendations

5.3.2.1 Stencil Opening Size for Solderball Pads on PCB

Warpage of the PCB and the package may cause solderjoint quality issues at the surface mount. Therefore, it is recommended that the stencil opening sizes be adjusted to compensate for the warpage. The recommendation is for the stencil aperture of the solderballs to be kept at the same size as the pads.

5.3.2.2 Reflow Profile

A reference reflow profile is given below. Please note the following when using RoHS/lead-free solder (SAC105/305/405 Tin-Silver-Cu):

- The final reflow temperature profile will depend on the type of solder paste and chemistry of flux used in the SMT process. Modifications to the reference reflow profile may be required in order to accommodate the requirements of the other components in the application.
- An oven with 10 heating zones or above is recommended.
- To ensure that the reflow profile meets the target specification on both sides of the board, a different profile and oven recipe for the first and second reflow may be required.
- Mechanical stiffening can be used to minimize board warpage during reflow.
- It is suggested to decrease temperature cooling rate to minimize board warpage.
- This reflow profile applies only to RoHS/lead-free (high temperature) soldering process and it should not be used for Eutectic solder packages. Damage may result if this condition is violated.
- Maximum 3 reflows are allowed on the same part.

Table 5-6 Recommended Board Solder Reflow Profile - RoHS/Lead-Free Solder

Profiling Stage	Temperature	Process Range
Overall Preheat	Room temp to 220°C	2 mins to 4 mins
Soaking Time	130°C to 170°C	Typical 60 – 80 seconds
Liquidus	220°C	Typical 60 – 80 seconds
Ramp Rate	Ramp up and Cooling	<2°C / second
Peak	Max. 245°C	235°C +/-5°C
Temperature at peak within 5°C	240°C to 245°C	10 – 30 seconds

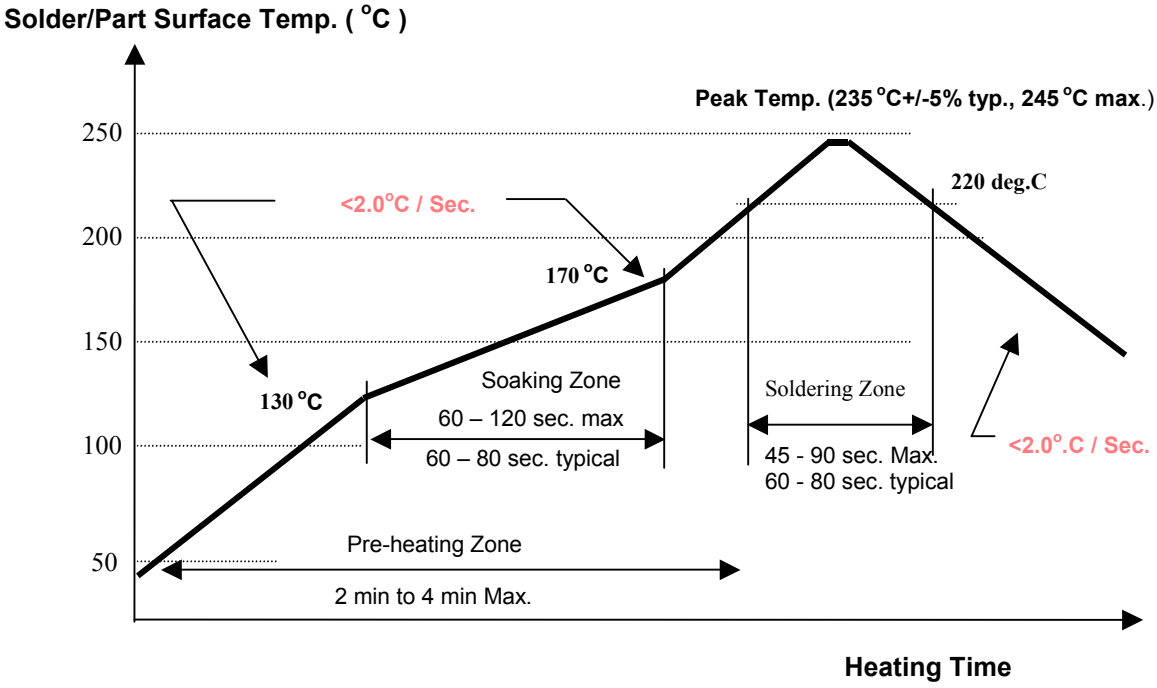

Figure 5-4 RoHS/Lead-Free Solder (SAC305/405 Tin-Silver-Copper) Reflow Profile

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Chapter 6
Power Management and ACPI

6.1 ACPI Power Management Implementation

This chapter describes the support for ACPI power management provided by the RD890. The RD890 system controller supports ACPI Revision 2.0. The hardware, system BIOS, and drivers of the RD890 have the logic required for meeting the power management specifications of PC2001, OnNow, and the Windows Logo Program and Device Requirements version 2.1. *Table 6-1, "ACPI States Supported by the RD890,"* describes the ACPI states supported by the RD890 system controller.

Table 6-1 ACPI States Supported by the RD890

ACPI State	Description
Processor States:	
S0/C0: Working State	Working State. The processor is executing instructions.
S0/C1: Halt	CPU Halt state. No instructions are executed. This state has the lowest latency on resume and contributes minimum power savings.
S0/C2: Stop Grant Caches Snoopable	Stop Grant or Cache Snoopable CPU state. This state offers more power savings but has a higher latency on resume than the C1 state.
S0/C3/C1e: Stop Grant Caches Snoopable	Processor is put into the Stop Grant state. Caches are still snoopable. The HyperTransport™ link may be disconnected and put into a low power state. System memory may be put into self-refresh.
System States:	
S1: Standby Powered On Suspend	System is in Standby mode. This state has low wakeup latency on resume. OEM support of this state is optional.
S3: Standby Suspend to RAM	System is off but context is saved to RAM. System memory is put into self-refresh.
S4: Hibernate Suspend to Disk	System is off but context is saved to disk. When the system transitions to the working state, the OS is resumed without a system re-boot.
S5: Soft Off	System is off. OS re-boots when the system transitions to the working state.
G3: Mechanical Off	Occurs when system power (AC or battery) is not present or is unable to keep the system in one of the other states.

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Chapter 7
Testability

7.1 Test Capability Features

The RD890 system controller has integrated test modes and capabilities. These test features cover both the ASIC and board level testing. The ASIC tests provide a very high fault coverage and low DPM (Defect Per Million) ratio of the part. The board level tests modes can be used for motherboard manufacturing and debug purposes. The following are the test modes of the RD890 system controller:

- Full scan implementation on the digital core logic that provides about 97% fault coverage through ATPG (Automatic Test Pattern Generation Vectors).
- Dedicated test logic for the on-chip custom memory macros to provide complete coverage on these modules.
- Improved access to the analog modules and PLLs in the RD890 system controller in order to allow full evaluation and characterization of these modules.
- A JTAG test mode (which is not entirely compliant to the IEEE 1149.1 standard) in order to allow board level testing of neighboring devices.
- An XOR TREE test mode on all the digital I/O's to allow for proper soldering verification at the board level.
- A VOH/VOL test mode on all digital I/O's to allow for proper verification of output high and output low voltages at the board level.

These test modes can be accessed through the settings on the instruction register of the JTAG circuitry.

7.2 Test Interface

Table 7-1 Pins on the Test Interface

Pin Name	Ball number	Type	Description
TESTMODE	A19	I	TEST_EN: Test Enable (IEEE 1149.1 test port reset)
PCIE_RESET_GPIO3	D19	I	TMS: Test Mode Select (IEEE 1149.1 test mode select)
I2C_DATA	C20	I	TDI: Test Mode Data In (IEEE 1149.1 data in)
I2C_CLK	B20	I	TCLK: Test Mode Clock (IEEE 1149.1 clock)
PWM_GPIO6	B16	O	TDO: Test Mode Data Out (IEEE 1149.1 data out)
PWM_GPIO4	A15	I	TEST_ODD: Control ODD output in VOH/VOL test
PWM_GPIO3	F16	I	TEST_EVEN: Control EVEN output in VOH/VOL test
POWERGOOD	A17	I	I/O Reset

7.3 XOR Tree

7.3.1 Brief Description of an XOR Tree

A sample of a generic XOR tree is shown in the figure below.

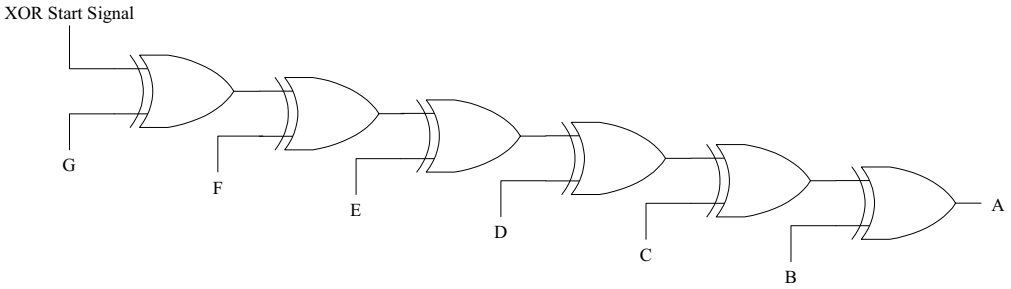

Figure 7-1 XOR Tree

Pin A is assigned to the output direction, and pins B through F are assigned to the input direction. It can be seen that after all pins B to F are assigned to logic 0 or 1, a logic change in any one of these pins will toggle the output pin A.

The following is the truth table for the XOR tree shown in *Figure 7-1* The XOR start signal is assumed to be logic 1.

Table 7-2 Example of an XOR Tree

Test Vector number	Input Pin G	Input Pin F	Input Pin E	Input Pin D	Input Pin C	Input Pin B	Output Pin A
1	0	0	0	0	0	0	1
2	1	0	0	0	0	0	0
3	1	1	0	0	0	0	1
4	1	1	1	0	0	0	0
5	1	1	1	1	0	0	1
6	1	1	1	1	1	0	0
7	1	1	1	1	1	1	1

7.3.2 Description of the XOR Tree for the RD890

The XOR start signal is applied at the TDI Pin of the JTAG circuitry and the output of the XOR tree is obtained at the TDO Pin. Refer to *Section 7.3.4* for the list of the signals included on the XOR tree. There is no specific order to these signals in the tree. A toggle of any of these balls in the XOR tree will cause the output to toggle.

7.3.3 XOR Tree Activation

To activate the XOR tree and run a XOR test, perform the sequence below:

1. Supply a 10MHz clock to I2C_CLK (Test Mode Clock) and a differential clock pair to the HT_REFCLKP1/N1, GFX_REFCLKP/N, GFX2_REFCLKP/N and GPP_REFCLKP/N pins.

2. Set POWERGOOD to 0.

3. Set TESTMODE to 1.

4. Set PCIE_RESET_GPIO2 to 0.

5. Wait 5 or more I2C_CLK cycles.

6. Load JTAG instruction register with the instruction 0001 1111.

7. Load JTAG instruction register with the instruction 0010 0000.

8. Load JTAG instruction register with the instruction 0000 1000.

9. Go to Run-Test_Idle state.

10. Set POWERGOOD to 1.

7.3.4 XOR Tree for the RD890

The XOR start signal is applied at the TDI Pin of the JTAG circuitry and the output of the XOR tree is obtained at the TDO Pin. Refer to *Table 7-3* for the list of the signals included on the XOR tree.

There is no specific order to these signals in the tree. A toggle of any of these balls in the XOR tree will cause the output to toggle. When the XOR tree is activated, any pin on the XOR tree must be either pulled down or pulled up to the I/O voltage of the pin. Only pins that are **not** on the XOR tree can be left floating.

When differential signal pairs are listed as single entries on the XOR tree, opposite input values should be applied to the two signals in each pair (e.g., for entry no. 1 on the tree, when "1" is applied to HT_RXCAD0P, "0" should be applied to HT_RXCAD0N).

Table 7-3 RD890 XOR Tree

No.	Pin Name	Ball Ref.
1	HT_RXCAD0P/N	AD28/AD27
2	HT_RXCAD1P/N	AC27/AC26
3	HT_RXCAD2P/N	AB28/AB27
4	HT_RXCAD3P/N	AA27/AA26
5	HT_RXCAD4P/N	W27/W26
6	HT_RXCAD5P/N	V28/V27
7	HT_RXCAD6P/N	U27/U26
8	HT_RXCAD7P/N	T28/T27
9	HT_RXCTL0P/N	R27/R26
10	HT_RXCAD8P/N	AD25/AD24
11	HT_RXCAD9P/N	AC24/AC23
12	HT_RXCAD10P/N	AB25/AB24
13	HT_RXCAD11P/N	AA24/AA23
14	HT_RXCAD12P/N	W24/W23
15	HT_RXCAD13P/N	V25/V24
16	HT_RXCAD14P/N	U24/U23
17	HT_RXCAD15P/N	T25/T24
18	HT_RXCTL1P/N	R24/R23
19	GFX_RX0P/N	E11/F11
20	GFX_RX1P/N	D10/E10
21	GFX_RX2P/N	E9/F9
22	GFX_RX3P/N	D8/E8
23	GFX_RX4P/N	E7/F7
24	GFX_RX5P/N	D6/E6
25	GFX_RX6P/N	B5/C5
26	GFX_RX7P/N	D2/D1
27	GFX_RX8P/N	F5/F4
28	GFX_RX9P/N	G6/G5
29	GFX_RX10P/N	H5/H4
30	GFX_RX11P/N	J6/J5
31	GFX_RX12P/N	K5/K4
32	GFX_RX13P/N	L6/L5
33	GFX_RX14P/N	M5/M4
34	GFX_RX15P/N	N6/N5
35	GFX2_RX0P/N	P5/P4
36	GFX2_RX1P/N	R6/R5
37	GFX2_RX2P/N	T5/T4
38	GFX2_RX3P/N	U6/U5
39	GFX2_RX4P/N	V5/V4
40	GFX2_RX5P/N	W6/W5
41	GFX2_RX6P/N	Y5/Y4
42	GFX2_RX7P/N	AA6/AA5
43	GFX2_RX8P/N	AB5/AB4
44	GFX2_RX9P/N	AD2/AD1
45	GFX2_RX10P/N	AF2/AF1
46	GFX2_RX11P/N	AF5/AG5
47	GFX2_RX12P/N	AD6/AE6
48	GFX2_RX13P/N	AC7/AD7
49	GFX2_RX14P/N	AD8/AE8
50	GFX2_RX15P/N	AC9/AD9
51	GPP_RX0P/N	AH20/AG20
52	GPP_RX1P/N	AD19/AC19
53	GPP_RX2P/N	AE18/AD18
54	GPP_RX3P/N	AD17/AC17
55	GPP_RX4P/N	AE16/AD16
56	GPP_RX5P/N	AD15/AC15

No.	Pin Name	Ball Ref.
57	SB_RX0P/N	AG26/AH26
58	SB_RX1P/N	AF25/AG25
59	SB_RX2P/N	AD22/AE22
60	SB_RX3P/N	AC21/AD21
61	GPP_RX6P/N	AE14/AD14
62	GPP_RX7P/N	AD13/AC13
63	GPP_RX8P/N	AE12/AD12
64	GPP_RX9P/N	AD11/AC11
65	PWM_GPIO1	E16
66	PWM_GPIO2	B15
67	PWM_GPIO3	F16
68	PWM_GPIO4	A15
69	PWM_GPIO5	C16
70	PCIE_RESET_GPIO1	B19
71	PCIE_RESET_GPIO4	E19
72	PCIE_RESET_GPIO5	E17
73	DFT_GPIO0	B26
74	DFT_GPIO1	A25
75	DFT_GPIO2	B24
76	DFT_GPIO3	B25
77	DFT_GPIO4	B23
78	DFT_GPIO5	A23
79	DBG_GPIO0	C22
80	DBG_GPIO1	B22
81	DBG_GPIO2	B21
82	DBG_GPIO3	A21
83	ALLOW_LDTSTOP	D21
84	LDTSTOP#	E15

7.4 VOH/VOL Test

7.4.1 Brief Description of a VOH/VOL Tree

The VOH/VOL logic provides signal output on I/O's when test patterns are applied to the TEST_ODD and TEST_EVEN pins. A sample of a generic VOH/VOL tree is shown in the figure below.

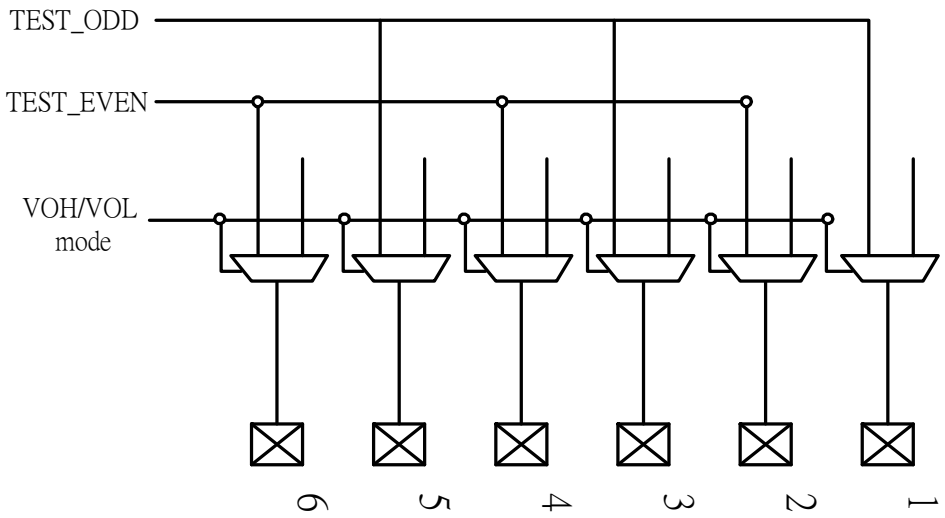

Figure 7-2 Sample of a Generic VOH/VOL Tree

The following is the truth table for the above VOH/VOL tree.

Table 7-4 Truth Table for the VOH/VOL Tree Outputs

Test Vector Number	TEST_ODD Input	TEST_EVEN Input	Output Pin 1	Output Pin 2	Output Pin 3	Output Pin 4	Output Pin 5	Output Pin 6
1	0	0	0	0	0	0	0	0
2	0	1	0	1	0	1	0	1
3	1	0	1	0	1	0	1	0
4	1	1	1	1	1	1	1	1

Refer to *Table 7-5* below for the list of pins that are on the VOH/VOL tree.

7.4.2 VOH/VOL Tree Activation

To activate the VOH/VOL tree and run a VOH/VOL test, perform the sequence below:

1. Supply a 10MHz clock to I2C_CLK (Test Mode Clock) and a differential clock pair to the HT_REFCLKP1/N1, GFX_REFCLKP/N, GFX2_REFCLKP/N and GPP_REFCLKP/N pins.
2. Set POWERGOOD to 0.
3. Set TESTMODE to 1.
4. Set PCIE_RESET_GPIO2 to 0.
5. Wait 5 or more I2C_CLK cycles.
6. Load JTAG instruction register with the instruction 0001 1111.
7. Load JTAG instruction register with the instruction 0010 0000.
8. Load JTAG instruction register with the instruction 0101 1101.
9. Go to Run-Test_Idle state.
10. Set POWERGOOD to 1.

7.4.3 VOH/VOL pin list

Table 7-5 below shows the RD890 VOH/VOL Tree. There is no specific order of connection. Under the Control column, an “Odd” or “Even” indicates that the logical output of the pin is same as the input to the “TEST_ODD” or the “TEST_EVEN” pin respectively.

When a differential signal pair appear in the table as a single entry, the output of the positive (“P”) pin is indicated in the Control column (see last paragraph for explanations) and the output of the negative pin (“N”) will be of the opposite value. E.g., for entry no. 1 on the tree, when TEST_EVEN is 1, HT_TXCAD0P will give a value of 1 and HT_TXCAD0N will give a value of 0.

Table 7-5 RD890 VOH/VOL Tree

No.	Pin Name	Ball Ref.	Control
1	HT_TXCAD0P/N	E26/E27	Even
2	HT_TXCAD1P/N	F27/F28	Odd
3	HT_TXCAD2P/N	G26/G27	Even
4	HT_TXCAD3P/N	H27/H28	Odd
5	HT_TXCAD4P/N	K27/K28	Even
6	HT_TXCAD5P/N	L26/L27	Odd
7	HT_TXCAD6P/N	M27/M28	Even
8	HT_TXCAD7P/N	N26/N27	Odd
9	HT_TXCTL0P/N	P27/P28	Even
10	HT_TXCAD8P/N	E23/E24	Odd
11	HT_TXCAD9P/N	F24/F25	Even
12	HT_TXCAD10P/N	G23/G24	Odd
13	HT_TXCAD11P/N	H24/H25	Even
14	HT_TXCAD12P/N	K24/K25	Odd
15	HT_TXCAD13P/N	L23/L24	Even
16	HT_TXCAD14P/N	M24/M25	Odd
17	HT_TXCAD15P/N	N23/N24	Even
18	HT_TXCTL1P/N	P24/P25	Odd
19	GFX_TX0P/N	B11/C11	Even
20	GFX_TX1P/N	A10/B10	Odd
21	GFX_TX2P/N	B9/C9	Even
22	GFX_TX3P/N	A8/B8	Odd
23	GFX_TX4P/N	B7/C7	Even
24	GFX_TX5P/N	A6/B6	Odd
25	GFX_TX6P/N	A4/B4	Even
26	GFX_TX7P/N	E3/E2	Odd
27	GFX_TX8P/N	F2/F1	Even
28	GFX_TX9P/N	G3/G2	Odd
29	GFX_TX10P/N	H2/H1	Even
30	GFX_TX11P/N	J3/J2	Odd
31	GFX_TX12P/N	K2/K1	Even
32	GFX_TX13P/N	L3/L2	Odd
33	GFX_TX14P/N	M2/M1	Even
34	GFX_TX15P/N	N3/N2	Odd
35	GFX2_TX0P/N	P2/P1	Even
36	GFX2_TX1P/N	R3/R2	Odd
37	GFX2_TX2P/N	T2/T1	Even
38	GFX2_TX3P/N	U3/U2	Odd
39	GFX2_TX4P/N	V2/V1	Even
40	GFX2_TX5P/N	W3/W2	Odd
41	GFX2_TX6P/N	Y2/Y1	Even
42	GFX2_TX7P/N	AA3/AA2	Odd
43	GFX2_TX8P/N	AB2/AB1	Even
44	GFX2_TX9P/N	AC3/AC2	Odd
45	GFX2_TX10P/N	AE3/AE2	Even
46	GFX2_TX11P/N	AG4/AH4	Odd
47	GFX2_TX12P/N	AG6/AH6	Even
48	GFX2_TX13P/N	AF7/AG7	Odd
49	GFX2_TX14P/N	AG8/AH8	Even
50	GFX2_TX15P/N	AF9/AG9	Odd
51	GPP_TX0P/N	AG19/AF19	Even
52	GPP_TX1P/N	AH18/AG18	Odd
53	GPP_TX2P/N	AG17/AF17	Even
54	GPP_TX3P/N	AH16/AG16	Odd
55	GPP_TX4P/N	AG15/AF15	Even
56	GPP_TX5P/N	AH14/AG14	Odd
57	SB_TX0P/N	AG24/AH24	Even
58	SB_TX1P/N	AF23/AG23	Odd

No.	Pin Name	Ball Ref.	Control
59	SB_TX2P/N	AF21/AG21	Even
60	SB_TX3P/N	AG22/AH22	Odd
61	GPP_TX6P/N	AG13/AF13	Even
62	GPP_TX7P/N	AH12/AG12	Odd
63	GPP_TX8P/N	AG11/AF11	Even
64	GPP_TX9P/N	AH10/AG10	Odd
65	PWM_GPIO1	E16	Even
66	PWM_GPIO2	B15	Odd
67	PWM_GPIO5	C16	Even
68	PCIE_RESET_GPIO1	B19	Odd
69	PCIE_RESET_GPIO4	E19	Even
70	PCIE_RESET_GPIO5	E17	Odd
71	DFT_GPIO0	B26	Even
72	DFT_GPIO1	A25	Odd
73	DFT_GPIO2	B24	Even
74	DFT_GPIO3	B25	Odd
75	DFT_GPIO4	B23	Even
76	DFT_GPIO5	A23	Odd
77	DBG_GPIO0	C22	Even
78	DBG_GPIO1	B22	Odd
79	DBG_GPIO2	B21	Even
80	DBG_GPIO3	A21	Odd
81	ALLOW_LDTSTOP	D21	Even
82	LDTSTOP#	E15	Odd

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Appendix A
Pin Listings

This appendix contains pin listings for the RD890 sorted in different ways. To go to the listing of interest, use the linked cross-references below:

"RD890 Pin Listing Sorted by Ball Reference" on page A-2

"RD890 Pin Listing Sorted by Pin Name" on page A-9

A.1 RD890 Pin Listing Sorted by Ball Reference

Table A-1 RD890 Pin Listing Sorted by Ball Reference

Ball #	Ball Name
A10	GFX_TX1P
A11	VSS
A12	VDDA18PCIE
A13	VDDA18PCIE
A14	VSS
A15	PWM_GPIO4
A16	VSS
A17	POWERGOOD
A18	VDD18
A19	TESTMODE
A20	VSS
A21	DBG_GPIO3
A22	VSS
A23	DFT_GPIO5
A24	VSS
A25	DFT_GPIO1
A26	VSS
A3	VDDPCIE
A4	GFX_TX6P
A5	VSS
A6	GFX_TX5P
A7	VSS
A8	GFX_TX3P
A9	VSS
AA1	VSS
AA10	VDDPCIE
AA11	VSS
AA12	VDDPCIE
AA13	VSS
AA14	GPP_REFCLKN
AA15	GPP_REFCLKP
AA16	VDDPCIE
AA17	VSS
AA18	VDDPCIE
AA19	VSS
AA2	GFX2_TX7N
AA20	VSS
AA21	THERMALDIODE_N
AA22	VDDHT
AA23	HT_RXCAD11N
AA24	HT_RXCAD11P
AA25	VSS
AA26	HT_RXCAD3N
AA27	HT_RXCAD3P
AA28	VSS
AA3	GFX2_TX7P
AA4	VSS
AA5	GFX2_RX7N
AA6	GFX2_RX7P
AA7	VSS
AA8	VDDPCIE
AA9	VSS
AB1	GFX2_TX8N
AB10	VSS
AB11	VDDPCIE
AB12	VSS
AB13	VDDPCIE
AB14	VSS
AB15	VDDPCIE
AB16	VSS
AB17	VDDPCIE
AB18	VSS
AB19	VDDPCIE
AB2	GFX2_TX8P
AB20	VSS
AB21	VSS
AB22	VDDHT
AB23	VSS
AB24	HT_RXCAD10N
AB25	HT_RXCAD10P
AB26	VSS
AB27	HT_RXCAD2N
AB28	HT_RXCAD2P
AB3	VSS
AB4	GFX2_RX8N
AB5	GFX2_RX8P
AB6	VSS
AB7	VDDPCIE
AB8	VSS
AB9	VDDPCIE
AC1	VSS
AC10	VSS
AC11	GPP_RX9N
AC12	VSS
AC13	GPP_RX7N
AC14	VSS
AC15	GPP_RX5N
AC16	VSS
AC17	GPP_RX3N
AC18	VSS
AC19	GPP_RX1N
AC2	GFX2_TX9N
AC20	VSS
AC21	SB_RX3P
AC22	VDDHT
AC23	HT_RXCAD9N
AC24	HT_RXCAD9P
AC25	VSS
AC26	HT_RXCAD1N
AC27	HT_RXCAD1P
AC28	VSS
AC3	GFX2_TX9P

Ball #	Ball Name
AC4	VSS
AC5	VSS
AC6	VDDPCIE
AC7	GFX2_RX13P
AC8	VSS
AC9	GFX2_RX15P
AD1	GFX2_RX9N
AD10	PCE_RCALRN
AD11	GPP_RX9P
AD12	GPP_RX8N
AD13	GPP_RX7P
AD14	GPP_RX6N
AD15	GPP_RX5P
AD16	GPP_RX4N
AD17	GPP_RX3P
AD18	GPP_RX2N
AD19	GPP_RX1P
AD2	GFX2_RX9P
AD20	PCE_BCALRN
AD21	SB_RX3N
AD22	SB_RX2P
AD23	VDDHT
AD24	HT_RXCAD8N
AD25	HT_RXCAD8P
AD26	VSS
AD27	HT_RXCAD0N
AD28	HT_RXCAD0P
AD3	VSS
AD4	VSS
AD5	VDDPCIE
AD6	GFX2_RX12P
AD7	GFX2_RX13N
AD8	GFX2_RX14P
AD9	GFX2_RX15N
AE1	VSS
AE10	PCE_RCALRP
AE11	VSS
AE12	GPP_RX8P
AE13	VSS
AE14	GPP_RX6P
AE15	VSS
AE16	GPP_RX4P
AE17	VSS
AE18	GPP_RX2P
AE19	VSS
AE2	GFX2_TX10N
AE20	PCE_BCALRP
AE21	VSS
AE22	SB_RX2N
AE23	VSS
AE24	VDDHT
AE25	VDDHT
AE26	VDDHT
AE27	VDDHT
AE28	VDDHT
AE3	GFX2_TX10P
AE4	VDDPCIE
AE5	VSS
AE6	GFX2_RX12N
AE7	VSS
AE8	GFX2_RX14N
AE9	VSS
AF1	GFX2_RX10N
AF10	VSS
AF11	GPP_TX8N
AF12	VSS
AF13	GPP_TX6N
AF14	VSS
AF15	GPP_TX4N
AF16	VSS
AF17	GPP_TX2N
AF18	VSS
AF19	GPP_TX0N
AF2	GFX2_RX10P
AF20	VSS
AF21	SB_TX2P
AF22	VSS
AF23	SB_TX1P
AF24	VSS
AF25	SB_RX1P
AF26	VSS
AF27	VDDHT
AF28	VSS
AF3	VDDPCIE
AF4	VSS
AF5	GFX2_RX11P
AF6	VSS
AF7	GFX2_TX13P
AF8	VSS
AF9	GFX2_TX15P
AG10	GPP_TX9N
AG11	GPP_TX8P
AG12	GPP_TX7N
AG13	GPP_TX6P
AG14	GPP_TX5N
AG15	GPP_TX4P
AG16	GPP_TX3N
AG17	GPP_TX2P
AG18	GPP_TX1N
AG19	GPP_TX0P
AG2	VDDPCIE
AG20	GPP_RX0N
AG21	SB_TX2N
AG22	SB_TX3P
AG23	SB_TX1N
AG24	SB_TX0P
AG25	SB_RX1N
AG26	SB_RX0P
AG27	VSS
AG3	VSS
AG4	GFX2_TX11P

Ball #	Ball Name
AG5	GFX2_RX11N
AG6	GFX2_TX12P
AG7	GFX2_TX13N
AG8	GFX2_TX14P
AG9	GFX2_TX15N
AH10	GPP_TX9P
AH11	VSS
AH12	GPP_TX7P
AH13	VSS
AH14	GPP_TX5P
AH15	VSS
AH16	GPP_TX3P
AH17	VSS
AH18	GPP_TX1P
AH19	VSS
AH20	GPP_RX0P
AH21	VSS
AH22	SB_TX3N
AH23	VSS
AH24	SB_TX0N
AH25	VSS
AH26	SB_RX0N
AH3	VSS
AH4	GFX2_TX11N
AH5	VSS
AH6	GFX2_TX12N
AH7	VSS
AH8	GFX2_TX14N
AH9	VSS
B10	GFX_TX1N
B11	GFX_TX0P
B12	VDDA18PCIE
B13	VDDA18PCIE
B14	VSS
B15	PWM_GPIO2
B16	PWM_GPIO6

Ball #	Ball Name
B17	OSCIN
B18	VDD18
B19	PCIE_RESET_GPIO 1
B2	VDDPCIE
B20	I2C_CLK
B21	DBG_GPIO2
B22	DBG_GPIO1
B23	DFT_GPIO4
B24	DFT_GPIO2
B25	DFT_GPIO3
B26	DFT_GPIO0
B27	VSS
B3	VSS
B4	GFX_TX6N
B5	GFX_RX6P
B6	GFX_TX5N
B7	GFX_TX4P
B8	GFX_TX3N
B9	GFX_TX2P
C1	VDDPCIE
C10	VSS
C11	GFX_TX0N
C12	VDDA18PCIE
C13	VDDA18PCIE
C14	VSS
C15	VSS
C16	PWM_GPIO5
C17	VSS
C18	VDD18
C19	VSS
C2	VSS
C20	I2C_DATA
C21	VSS
C22	DBG_GPIO0
C23	VSS
C24	VDDHTTX

Ball #	Ball Name
C25	VDDHTTX
C26	VDDHTTX
C27	VDDHTTX
C28	VDDHTTX
C3	VDDPCIE
C4	VSS
C5	GFX_RX6N
C6	VSS
C7	GFX_TX4N
C8	VSS
C9	GFX_TX2N
D1	GFX_RX7N
D10	GFX_RX1P
D11	VSS
D12	VDDA18PCIE
D13	VDDA18PCIE
D14	VSS
D15	SYSRESET#
D16	VSS
D17	PCIE_RESET_GPIO 2
D18	VDD18
D19	PCIE_RESET_GPIO 3
D2	GFX_RX7P
D20	VSS
D21	ALLOW_LDTSTOP
D22	VDDHTTX
D23	VDDHTTX
D24	HT_RXCALN
D25	HT_RXCALP
D26	VSS
D27	HT_TXCALN
D28	HT_TXCALP
D3	VSS
D4	VDDPCIE
D5	VSS

Ball #	Ball Name
D6	GFX_RX5P
D7	VSS
D8	GFX_RX3P
D9	VSS
E1	VSS
E10	GFX_RX1N
E11	GFX_RX0P
E12	VDDA18PCIE
E13	VDDA18PCIE
E14	PCE_TCALRN
E15	LDTSTOP#
E16	PWM_GPIO1
E17	PCIE_RESET_GPIO 5
E18	VDD18
E19	PCIE_RESET_GPIO 4
E2	GFX_TX7N
E20	VSS
E21	STRP_DATA
E22	VDDHTTX
E23	HT_TXCAD8P
E24	HT_TXCAD8N
E25	VSS
E26	HT_TXCAD0P
E27	HT_TXCAD0N
E28	VSS
E3	GFX_TX7P
E4	VSS
E5	VDDPCIE
E6	GFX_RX5N
E7	GFX_RX4P
E8	GFX_RX3N
E9	GFX_RX2P
F1	GFX_TX8N
F10	VSS
F11	GFX_RX0N

Ball #	Ball Name
F12	VDDA18PCIE
F13	VDDA18PCIE
F14	PCE_TCALRP
F15	VSS
F16	PWM_GPIO3
F17	VSS
F18	VSS
F19	VSS
F2	GFX_TX8P
F20	VSS
F21	VSS
F22	VDDHTTX
F23	VSS
F24	HT_TXCAD9P
F25	HT_TXCAD9N
F26	VSS
F27	HT_TXCAD1P
F28	HT_TXCAD1N
F3	VSS
F4	GFX_RX8N
F5	GFX_RX8P
F6	VDDPCIE
F7	GFX_RX4N
F8	VSS
F9	GFX_RX2N
G1	VSS
G10	VDDPCIE
G11	VSS
G12	VDDA18PCIE
G13	VDDA18PCIE
G14	VDDA18PCIE
G15	VSS
G16	VSS
G17	VSS
G18	VSS
G19	VSS

Ball #	Ball Name
G2	GFX_TX9N
G20	VSS
G21	VDDA18HTPLL
G22	VDDHTTX
G23	HT_TXCAD10P
G24	HT_TXCAD10N
G25	VSS
G26	HT_TXCAD2P
G27	HT_TXCAD2N
G28	VSS
G3	GFX_TX9P
G4	VSS
G5	GFX_RX9N
G6	GFX_RX9P
G7	VDDPCIE
G8	VDDPCIE
G9	VSS
H1	GFX_TX10N
H10	VSS
H11	VDDPCIE
H12	VDDA18PCIE
H13	VDDA18PCIE
H14	VDDA18PCIE
H15	VSS
H16	VSS
H17	VSS
H18	VSS
H19	VSS
H2	GFX_TX10P
H20	VSS
H21	VSS
H22	VDDHTTX
H23	VSS
H24	HT_TXCAD11P
H25	HT_TXCAD11N
H26	VSS

Ball #	Ball Name
H27	HT_TXCAD3P
H28	HT_TXCAD3N
H3	VSS
H4	GFX_RX10N
H5	GFX_RX10P
H6	VSS
H7	VDDPCIE
H8	GFX_REFCLKN
H9	VDDPCIE
J1	VSS
J2	GFX_TX11N
J21	HT_REFCLKN
J22	VSS
J23	HT_TXCLK1P
J24	HT_TXCLK1N
J25	VSS
J26	HT_TXCLK0P
J27	HT_TXCLK0N
J28	VSS
J3	GFX_TX11P
J4	VSS
J5	GFX_RX11N
J6	GFX_RX11P
J7	VSS
J8	GFX_REFCLKP
K1	GFX_TX12N
K2	GFX_TX12P
K21	HT_REFCLKP
K22	VDDHT
K23	VSS
K24	HT_TXCAD12P
K25	HT_TXCAD12N
K26	VSS
K27	HT_TXCAD4P
K28	HT_TXCAD4N
K3	VSS

Ball #	Ball Name
K4	GFX_RX12N
K5	GFX_RX12P
K6	VSS
K7	VDDPCIE
K8	VSS
L1	VSS
L11	VDDA18PCIE
L12	VSS
L13	VSS
L14	VDDC
L15	VSS
L16	VDDC
L17	VSS
L18	VSS
L2	GFX_TX13N
L21	VDDHT
L22	VSS
L23	HT_TXCAD13P
L24	HT_TXCAD13N
L25	VSS
L26	HT_TXCAD5P
L27	HT_TXCAD5N
L28	VSS
L3	GFX_TX13P
L4	VSS
L5	GFX_RX13N
L6	GFX_RX13P
L7	VSS
L8	VDDPCIE
M1	GFX_TX14N
M11	VSS
M12	VSS
M13	VDDC
M14	VSS
M15	VDDC
M16	VSS

Ball #	Ball Name
M17	VSS
M18	VSS
M2	GFX_TX14P
M21	VSS
M22	VDDHT
M23	VSS
M24	HT_TXCAD14P
M25	HT_TXCAD14N
M26	VSS
M27	HT_TXCAD6P
M28	HT_TXCAD6N
M3	VSS
M4	GFX_RX14N
M5	GFX_RX14P
M6	VSS
M7	VDDPCIE
M8	VSS
N1	VSS
N11	VSS
N12	VDDC
N13	VSS
N14	VDDC
N15	VSS
N16	VDDC
N17	VSS
N18	VSS
N2	GFX_TX15N
N21	VDDHT
N22	VSS
N23	HT_TXCAD15P
N24	HT_TXCAD15N
N25	VSS
N26	HT_TXCAD7P
N27	HT_TXCAD7N
N28	VSS
N3	GFX_TX15P

Ball #	Ball Name
N4	VSS
N5	GFX_RX15N
N6	GFX_RX15P
N7	VSS
N8	VDDPCIE
P1	GFX2_TX0N
P11	VSS
P12	VSS
P13	VDDC
P14	VSS
P15	VDDC
P16	VSS
P17	VDDC
P18	VSS
P2	GFX2_TX0P
P21	VSS
P22	VDDHT
P23	VSS
P24	HT_TXCTL1P
P25	HT_TXCTL1N
P26	VSS
P27	HT_TXCTL0P
P28	HT_TXCTL0N
P3	VSS
P4	GFX2_RX0N
P5	GFX2_RX0P
P6	VSS
P7	VDDPCIE
P8	VSS
R1	VSS
R11	VSS
R12	VDDC
R13	VSS
R14	VDDC
R15	VSS
R16	VDDC

Ball #	Ball Name
R17	VSS
R18	VSS
R2	GFX2_TX1N
R21	VDDHT
R22	VSS
R23	HT_RXCTL1N
R24	HT_RXCTL1P
R25	VSS
R26	HT_RXCTL0N
R27	HT_RXCTL0P
R28	VSS
R3	GFX2_TX1P
R4	VSS
R5	GFX2_RX1N
R6	GFX2_RX1P
R7	VSS
R8	VDDPCIE
T1	GFX2_TX2N
T11	VSS
T12	VSS
T13	VDDC
T14	VSS
T15	VDDC
T16	VSS
T17	VDDC
T18	VSS
T2	GFX2_TX2P
T21	VSS
T22	VDDHT
T23	VSS
T24	HT_RXCAD15N
T25	HT_RXCAD15P
T26	VSS
T27	HT_RXCAD7N
T28	HT_RXCAD7P
T3	VSS

Ball #	Ball Name
T4	GFX2_RX2N
T5	GFX2_RX2P
T6	VSS
T7	VDDPCIE
T8	VSS
U1	VSS
U11	VSS
U12	VSS
U13	VSS
U14	VDDC
U15	VSS
U16	VDDC
U17	VSS
U18	VSS
U2	GFX2_TX3N
U21	VDDHT
U22	VSS
U23	HT_RXCAD14N
U24	HT_RXCAD14P
U25	VSS
U26	HT_RXCAD6N
U27	HT_RXCAD6P
U28	VSS
U3	GFX2_TX3P
U4	VSS
U5	GFX2_RX3N
U6	GFX2_RX3P
U7	VSS
U8	GFX2_REFCLKN
V1	GFX2_TX4N
V11	VDDA18PCIE
V12	VSS
V13	VSS
V14	VSS
V15	VSS
V16	VSS

Ball #	Ball Name
V17	VSS
V18	VDDA18PCIE
V2	GFX2_TX4P
V21	VSS
V22	VDDHT
V23	VSS
V24	HT_RXCAD13N
V25	HT_RXCAD13P
V26	VSS
V27	HT_RXCAD5N
V28	HT_RXCAD5P
V3	VSS
V4	GFX2_RX4N
V5	GFX2_RX4P
V6	VSS
V7	VDDPCIE
V8	GFX2_REFCLKP
W1	VSS
W2	GFX2_TX5N
W21	VDDHT
W22	VSS
W23	HT_RXCAD12N
W24	HT_RXCAD12P
W25	VSS
W26	HT_RXCAD4N
W27	HT_RXCAD4P
W28	VSS
W3	GFX2_TX5P
W4	VSS
W5	GFX2_RX5N
W6	GFX2_RX5P
W7	VSS
W8	VDDPCIE
Y1	GFX2_TX6N
Y2	GFX2_TX6P
Y21	THERMALDIODE_P

Ball #	Ball Name
Y22	VDDHT
Y23	VSS
Y24	HT_RXCLK1N
Y25	HT_RXCLK1P
Y26	VSS
Y27	HT_RXCLK0N
Y28	HT_RXCLK0P
Y3	VSS
Y4	GFX2_RX6N
Y5	GFX2_RX6P
Y6	VSS
Y7	VDDPCIE
Y8	VSS

A.2 RD890 Pin Listing Sorted by Pin Name

Ball Name	Ball #
ALLOW_LDTSTOP	D21
DBG_GPIO0	C22
DBG_GPIO1	B22
DBG_GPIO2	B21
DBG_GPIO3	A21
DFT_GPIO0	B26
DFT_GPIO1	A25
DFT_GPIO2	B24
DFT_GPIO3	B25
DFT_GPIO4	B23
DFT_GPIO5	A23
GFX_REFCLKN	H8
GFX_REFCLKP	J8
GFX_RX0N	F11
GFX_RX0P	E11
GFX_RX10N	H4
GFX_RX10P	H5
GFX_RX11N	J5
GFX_RX11P	J6
GFX_RX12N	K4
GFX_RX12P	K5
GFX_RX13N	L5
GFX_RX13P	L6
GFX_RX14N	M4
GFX_RX14P	M5
GFX_RX15N	N5
GFX_RX15P	N6
GFX_RX1N	E10
GFX_RX1P	D10
GFX_RX2N	F9
GFX_RX2P	E9
GFX_RX3N	E8
GFX_RX3P	D8
GFX_RX4N	F7
GFX_RX4P	E7

Ball Name	Ball #
GFX_RX5N	E6
GFX_RX5P	D6
GFX_RX6N	C5
GFX_RX6P	B5
GFX_RX7N	D1
GFX_RX7P	D2
GFX_RX8N	F4
GFX_RX8P	F5
GFX_RX9N	G5
GFX_RX9P	G6
GFX_TX0N	C11
GFX_TX0P	B11
GFX_TX10N	H1
GFX_TX10P	H2
GFX_TX11N	J2
GFX_TX11P	J3
GFX_TX12N	K1
GFX_TX12P	K2
GFX_TX13N	L2
GFX_TX13P	L3
GFX_TX14N	M1
GFX_TX14P	M2
GFX_TX15N	N2
GFX_TX15P	N3
GFX_TX1N	B10
GFX_TX1P	A10
GFX_TX2N	C9
GFX_TX2P	B9
GFX_TX3N	B8
GFX_TX3P	A8
GFX_TX4N	C7
GFX_TX4P	B7
GFX_TX5N	B6
GFX_TX5P	A6
GFX_TX6N	B4

Ball Name	Ball #
GFX_TX6P	A4
GFX_TX7N	E2
GFX_TX7P	E3
GFX_TX8N	F1
GFX_TX8P	F2
GFX_TX9N	G2
GFX_TX9P	G3
GFX2_REFCLKN	U8
GFX2_REFCLKP	V8
GFX2_RX0N	P4
GFX2_RX0P	P5
GFX2_RX10N	AF1
GFX2_RX10P	AF2
GFX2_RX11N	AG5
GFX2_RX11P	AF5
GFX2_RX12N	AE6
GFX2_RX12P	AD6
GFX2_RX13N	AD7
GFX2_RX13P	AC7
GFX2_RX14N	AE8
GFX2_RX14P	AD8
GFX2_RX15N	AD9
GFX2_RX15P	AC9
GFX2_RX1N	R5
GFX2_RX1P	R6
GFX2_RX2N	T4
GFX2_RX2P	T5
GFX2_RX3N	U5
GFX2_RX3P	U6
GFX2_RX4N	V4
GFX2_RX4P	V5
GFX2_RX5N	W5
GFX2_RX5P	W6
GFX2_RX6N	Y4
GFX2_RX6P	Y5

Ball Name	Ball #
GFX2_RX7N	AA5
GFX2_RX7P	AA6
GFX2_RX8N	AB4
GFX2_RX8P	AB5
GFX2_RX9N	AD1
GFX2_RX9P	AD2
GFX2_TX0N	P1
GFX2_TX0P	P2
GFX2_TX10N	AE2
GFX2_TX10P	AE3
GFX2_TX11N	AH4
GFX2_TX11P	AG4
GFX2_TX12N	AH6
GFX2_TX12P	AG6
GFX2_TX13N	AG7
GFX2_TX13P	AF7
GFX2_TX14N	AH8
GFX2_TX14P	AG8
GFX2_TX15N	AG9
GFX2_TX15P	AF9
GFX2_TX1N	R2
GFX2_TX1P	R3
GFX2_TX2N	T1
GFX2_TX2P	T2
GFX2_TX3N	U2
GFX2_TX3P	U3
GFX2_TX4N	V1
GFX2_TX4P	V2
GFX2_TX5N	W2
GFX2_TX5P	W3
GFX2_TX6N	Y1
GFX2_TX6P	Y2
GFX2_TX7N	AA2
GFX2_TX7P	AA3
GFX2_TX8N	AB1
GFX2_TX8P	AB2

Ball Name	Ball #
GFX2_TX9N	AC2
GFX2_TX9P	AC3
GPP_REFCLKN	AA14
GPP_REFCLKP	AA15
GPP_RX0N	AG20
GPP_RX0P	AH20
GPP_RX1N	AC19
GPP_RX1P	AD19
GPP_RX2N	AD18
GPP_RX2P	AE18
GPP_RX3N	AC17
GPP_RX3P	AD17
GPP_RX4N	AD16
GPP_RX4P	AE16
GPP_RX5N	AC15
GPP_RX5P	AD15
GPP_RX6N	AD14
GPP_RX6P	AE14
GPP_RX7N	AC13
GPP_RX7P	AD13
GPP_RX8N	AD12
GPP_RX8P	AE12
GPP_RX9N	AC11
GPP_RX9P	AD11
GPP_TX0N	AF19
GPP_TX0P	AG19
GPP_TX1N	AG18
GPP_TX1P	AH18
GPP_TX2N	AF17
GPP_TX2P	AG17
GPP_TX3N	AG16
GPP_TX3P	AH16
GPP_TX4N	AF15
GPP_TX4P	AG15
GPP_TX5N	AG14
GPP_TX5P	AH14

Ball Name	Ball #
GPP_TX6N	AF13
GPP_TX6P	AG13
GPP_TX7N	AG12
GPP_TX7P	AH12
GPP_TX8N	AF11
GPP_TX8P	AG11
GPP_TX9N	AG10
GPP_TX9P	AH10
HT_REFCLKN	J21
HT_REFCLKP	K21
HT_RXCAD0N	AD27
HT_RXCAD0P	AD28
HT_RXCAD10N	AB24
HT_RXCAD10P	AB25
HT_RXCAD11N	AA23
HT_RXCAD11P	AA24
HT_RXCAD12N	W23
HT_RXCAD12P	W24
HT_RXCAD13N	V24
HT_RXCAD13P	V25
HT_RXCAD14N	U23
HT_RXCAD14P	U24
HT_RXCAD15N	T24
HT_RXCAD15P	T25
HT_RXCAD1N	AC26
HT_RXCAD1P	AC27
HT_RXCAD2N	AB27
HT_RXCAD2P	AB28
HT_RXCAD3N	AA26
HT_RXCAD3P	AA27
HT_RXCAD4N	W26
HT_RXCAD4P	W27
HT_RXCAD5N	V27
HT_RXCAD5P	V28
HT_RXCAD6N	U26
HT_RXCAD6P	U27

Ball Name	Ball #
HT_RXCAD7N	T27
HT_RXCAD7P	T28
HT_RXCAD8N	AD24
HT_RXCAD8P	AD25
HT_RXCAD9N	AC23
HT_RXCAD9P	AC24
HT_RXCALN	D24
HT_RXCALP	D25
HT_RXCLK0N	Y27
HT_RXCLK0P	Y28
HT_RXCLK1N	Y24
HT_RXCLK1P	Y25
HT_RXCTL0N	R26
HT_RXCTL0P	R27
HT_RXCTL1N	R23
HT_RXCTL1P	R24
HT_TXCAD0N	E27
HT_TXCAD0P	E26
HT_TXCAD10N	G24
HT_TXCAD10P	G23
HT_TXCAD11N	H25
HT_TXCAD11P	H24
HT_TXCAD12N	K25
HT_TXCAD12P	K24
HT_TXCAD13N	L24
HT_TXCAD13P	L23
HT_TXCAD14N	M25
HT_TXCAD14P	M24
HT_TXCAD15N	N24
HT_TXCAD15P	N23
HT_TXCAD1N	F28
HT_TXCAD1P	F27
HT_TXCAD2N	G27
HT_TXCAD2P	G26
HT_TXCAD3N	H28
HT_TXCAD3P	H27

Ball Name	Ball #
HT_TXCAD4N	K28
HT_TXCAD4P	K27
HT_TXCAD5N	L27
HT_TXCAD5P	L26
HT_TXCAD6N	M28
HT_TXCAD6P	M27
HT_TXCAD7N	N27
HT_TXCAD7P	N26
HT_TXCAD8N	E24
HT_TXCAD8P	E23
HT_TXCAD9N	F25
HT_TXCAD9P	F24
HT_TXCALN	D27
HT_TXCALP	D28
HT_TXCLK0N	J27
HT_TXCLK0P	J26
HT_TXCLK1N	J24
HT_TXCLK1P	J23
HT_TXCTL0N	P28
HT_TXCTL0P	P27
HT_TXCTL1N	P25
HT_TXCTL1P	P24
I2C_CLK	B20
I2C_DATA	C20
LDTSTOP#	E15
OSCIN	B17
PCE_BCALRN	AD20
PCE_BCALRP	AE20
PCE_RCALRN	AD10
PCE_RCALRP	AE10
PCE_TCALRN	E14
PCE_TCALRP	F14
PCIE_RESET_GPIO 1	B19
PCIE_RESET_GPIO 2	D17

Ball Name	Ball #
PCIE_RESET_GPIO 3	D19
PCIE_RESET_GPIO 4	E19
PCIE_RESET_GPIO 5	E17
POWERGOOD	A17
PWM_GPIO1	E16
PWM_GPIO2	B15
PWM_GPIO3	F16
PWM_GPIO4	A15
PWM_GPIO5	C16
PWM_GPIO6	B16
SB_RX0N	AH26
SB_RX0P	AG26
SB_RX1N	AG25
SB_RX1P	AF25
SB_RX2N	AE22
SB_RX2P	AD22
SB_RX3N	AD21
SB_RX3P	AC21
SB_TX0N	AH24
SB_TX0P	AG24
SB_TX1N	AG23
SB_TX1P	AF23
SB_TX2N	AG21
SB_TX2P	AF21
SB_TX3N	AH22
SB_TX3P	AG22
STRP_DATA	E21
SYSRESET#	D15
TESTMODE	A19
THERMALDIODE_N	AA21
THERMALDIODE_P	Y21
VDD18	A18
VDD18	B18
VDD18	C18

Ball Name	Ball #
VDD18	D18
VDD18	E18
VDDA18HTPLL	G21
VDDA18PCIE	A12
VDDA18PCIE	A13
VDDA18PCIE	B12
VDDA18PCIE	B13
VDDA18PCIE	C12
VDDA18PCIE	C13
VDDA18PCIE	D12
VDDA18PCIE	D13
VDDA18PCIE	E12
VDDA18PCIE	E13
VDDA18PCIE	F12
VDDA18PCIE	F13
VDDA18PCIE	G12
VDDA18PCIE	G13
VDDA18PCIE	G14
VDDA18PCIE	H12
VDDA18PCIE	H13
VDDA18PCIE	H14
VDDA18PCIE	L11
VDDA18PCIE	V11
VDDA18PCIE	V18
VDDC	L14
VDDC	L16
VDDC	M13
VDDC	M15
VDDC	N12
VDDC	N14
VDDC	N16
VDDC	P13
VDDC	P15
VDDC	P17
VDDC	R12
VDDC	R14

Ball Name	Ball #
VDDC	R16
VDDC	T13
VDDC	T15
VDDC	T17
VDDC	U14
VDDC	U16
VDDHT	AA22
VDDHT	AB22
VDDHT	AC22
VDDHT	AD23
VDDHT	AE24
VDDHT	AE25
VDDHT	AE26
VDDHT	AE27
VDDHT	AE28
VDDHT	AF27
VDDHT	K22
VDDHT	L21
VDDHT	M22
VDDHT	N21
VDDHT	P22
VDDHT	R21
VDDHT	T22
VDDHT	U21
VDDHT	V22
VDDHT	W21
VDDHT	Y22
VDDHTTX	C24
VDDHTTX	C25
VDDHTTX	C26
VDDHTTX	C27
VDDHTTX	C28
VDDHTTX	D22
VDDHTTX	D23
VDDHTTX	E22
VDDHTTX	F22

Ball Name	Ball #
VDDHTTX	G22
VDDHTTX	H22
VDDPCIE	A3
VDDPCIE	AA10
VDDPCIE	AA12
VDDPCIE	AA16
VDDPCIE	AA18
VDDPCIE	AA8
VDDPCIE	AB11
VDDPCIE	AB13
VDDPCIE	AB15
VDDPCIE	AB17
VDDPCIE	AB19
VDDPCIE	AB7
VDDPCIE	AB9
VDDPCIE	AC6
VDDPCIE	AD5
VDDPCIE	AE4
VDDPCIE	AF3
VDDPCIE	AG2
VDDPCIE	B2
VDDPCIE	C1
VDDPCIE	C3
VDDPCIE	D4
VDDPCIE	E5
VDDPCIE	F6
VDDPCIE	G10
VDDPCIE	G7
VDDPCIE	G8
VDDPCIE	H11
VDDPCIE	H7
VDDPCIE	H9
VDDPCIE	K7
VDDPCIE	L8
VDDPCIE	M7
VDDPCIE	N8

Ball Name	Ball #
VDDPCIE	P7
VDDPCIE	R8
VDDPCIE	T7
VDDPCIE	V7
VDDPCIE	W8
VDDPCIE	Y7
VSS	A11
VSS	A14
VSS	A16
VSS	A20
VSS	A22
VSS	A24
VSS	A26
VSS	A5
VSS	A7
VSS	A9
VSS	AA1
VSS	AA11
VSS	AA13
VSS	AA17
VSS	AA19
VSS	AA20
VSS	AA25
VSS	AA28
VSS	AA4
VSS	AA7
VSS	AA9
VSS	AB10
VSS	AB12
VSS	AB14
VSS	AB16
VSS	AB18
VSS	AB20
VSS	AB21
VSS	AB23
VSS	AB26

Ball Name	Ball #
VSS	AB3
VSS	AB6
VSS	AB8
VSS	AC1
VSS	AC10
VSS	AC12
VSS	AC14
VSS	AC16
VSS	AC18
VSS	AC20
VSS	AC25
VSS	AC28
VSS	AC4
VSS	AC5
VSS	AC8
VSS	AD26
VSS	AD3
VSS	AD4
VSS	AE1
VSS	AE11
VSS	AE13
VSS	AE15
VSS	AE17
VSS	AE19
VSS	AE21
VSS	AE23
VSS	AE5
VSS	AE7
VSS	AE9
VSS	AF10
VSS	AF12
VSS	AF14
VSS	AF16
VSS	AF18
VSS	AF20
VSS	AF22

Ball Name	Ball #
VSS	AF24
VSS	AF26
VSS	AF28
VSS	AF4
VSS	AF6
VSS	AF8
VSS	AG27
VSS	AG3
VSS	AH11
VSS	AH13
VSS	AH15
VSS	AH17
VSS	AH19
VSS	AH21
VSS	AH23
VSS	AH25
VSS	AH3
VSS	AH5
VSS	AH7
VSS	AH9
VSS	B14
VSS	B27
VSS	B3
VSS	C10
VSS	C14
VSS	C15
VSS	C17
VSS	C19
VSS	C2
VSS	C21
VSS	C23
VSS	C4
VSS	C6
VSS	C8
VSS	D11
VSS	D14

Ball Name	Ball #
VSS	D16
VSS	D20
VSS	D26
VSS	D3
VSS	D5
VSS	D7
VSS	D9
VSS	E1
VSS	E20
VSS	E25
VSS	E28
VSS	E4
VSS	F10
VSS	F15
VSS	F17
VSS	F18
VSS	F19
VSS	F20
VSS	F21
VSS	F23
VSS	F26
VSS	F3
VSS	F8
VSS	G1
VSS	G11
VSS	G15
VSS	G16
VSS	G17
VSS	G18
VSS	G19
VSS	G20
VSS	G25
VSS	G28
VSS	G4
VSS	G9
VSS	H10

Ball Name	Ball #
VSS	H15
VSS	H16
VSS	H17
VSS	H18
VSS	H19
VSS	H20
VSS	H21
VSS	H23
VSS	H26
VSS	H3
VSS	H6
VSS	J1
VSS	J22
VSS	J25
VSS	J28
VSS	J4
VSS	J7
VSS	K23
VSS	K26
VSS	K3
VSS	K6
VSS	K8
VSS	L1
VSS	L12
VSS	L13
VSS	L15
VSS	L17
VSS	L18
VSS	L22
VSS	L25
VSS	L28
VSS	L4
VSS	L7
VSS	M11
VSS	M12
VSS	M14

Ball Name	Ball #
VSS	M16
VSS	M17
VSS	M18
VSS	M21
VSS	M23
VSS	M26
VSS	M3
VSS	M6
VSS	M8
VSS	N1
VSS	N11
VSS	N13
VSS	N15
VSS	N17
VSS	N18
VSS	N22
VSS	N25
VSS	N28
VSS	N4
VSS	N7
VSS	P11
VSS	P12
VSS	P14
VSS	P16
VSS	P18
VSS	P21
VSS	P23
VSS	P26
VSS	P3
VSS	P6
VSS	P8
VSS	R1
VSS	R11
VSS	R13
VSS	R15
VSS	R17

Ball Name	Ball #
VSS	R18
VSS	R22
VSS	R25
VSS	R28
VSS	R4
VSS	R7
VSS	T11
VSS	T12
VSS	T14
VSS	T16
VSS	T18
VSS	T21
VSS	T23
VSS	T26
VSS	T3
VSS	T6
VSS	T8
VSS	U1
VSS	U11
VSS	U12
VSS	U13
VSS	U15
VSS	U17
VSS	U18
VSS	U22
VSS	U25
VSS	U28
VSS	U4
VSS	U7
VSS	V12
VSS	V13
VSS	V14
VSS	V15
VSS	V16
VSS	V17
VSS	V21

Ball Name	Ball #
VSS	V23
VSS	V26
VSS	V3
VSS	V6
VSS	W1
VSS	W22
VSS	W25
VSS	W28
VSS	W4
VSS	W7
VSS	Y23
VSS	Y26
VSS	Y3
VSS	Y6
VSS	Y8

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Appendix B
Revision History

Rev. 3.00 (Jan 2012)

- First public release based on rev. 1.30 of the NDA version, with the following change:
  - Updated Section 3.5, “Clock Interface”: Made connection of GPP_REFCLKP/N mandatory.

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